



Association Suisse de Traitement
Thermique des Matériaux



ASTT 27.11.2015

Agenda

Day 27.11.2015

1. 09:30 – 09:35
2. 09:35 – 10:30
3. 10:30 – 11:45
4. 11:45 – 12:00

Welcome & Introduction

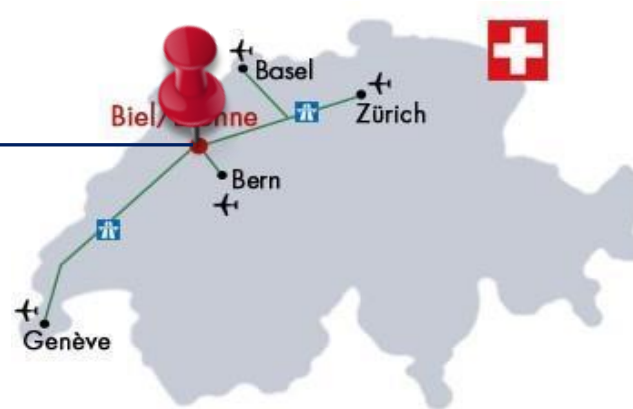
Posalux Technologies

Plant Tour

Engineering, Facility, Da Vinci Center

Discussions

Posalux SA - Switzerland



Founded in 1943, Posalux is a leading Suisse manufacturer for micro technologies for mass production.

Posalux is headquartered in Biel-Bienne, one of the most important cities of Switzerland, which is famous not only as a watch metropolis, but also as one of the most important centers for advanced technologies.

Global presence:

- Subsidiaries of Posalux in Germany, Korea and Taiwan
- Worldwide network of sales and service agents in major countries

Posalux – Business Strategy

- Best in class system solution provider to enhance and grow our customers business and become supplier of choice with mutual benefit and success
- Development and industrialization of standardized high-technology machines for mass production in niche markets
- Fulfill and exceed our customers expectations; internal & external
- Attract, develop and retain highly talented people to assure the long-term success of Posalux
- Foster national and international collaborations with Universities and Universities of applied sciences to increase the speed of innovations

Posalux Core Competencies

- Joint development of future applications with our customers, to meet and exceed product-process specifications
- Supply of highly accurate and productive equipment, 95% for export worldwide
- We provide complete solutions – not only machine tools
- Application knowledge and process support for our customers
- Service - active and very efficient worldwide
- Excellent knowledge of our worldwide markets

Posalux Customers

- Major customers are Automotive and Electronics with strong requirements
 - E.g. to reach automotive final goals : PPM 0km < 2 and vehicles warranties from 2 to 7 years
 - ✓ Quality first : $C_{pk} > 1,67$ / $C_p > 2,0$
 - ✓ FMEA process mandatory with customers, final concept and design validated in common with Posalux and customers
 - ✓ Common building for maintenance plans and setting
 - ✓ Posalux warranty from 18 to 24 months, service reactivity max 24h
 - ✓ Quality dossier, with measurements report by Posalux, arrived from customer equivalent or better devices
 - ✓ Individual traceability or post process devices integration...

POSALUX - 6 Technologies

PCB Micro Drilling and Routing



Micro Drilling & Routing

Milling machining



Milling machining

LASER Femto



LASER Femto

LASER Micro Jet



LASER Microjet

EDM micro-machining



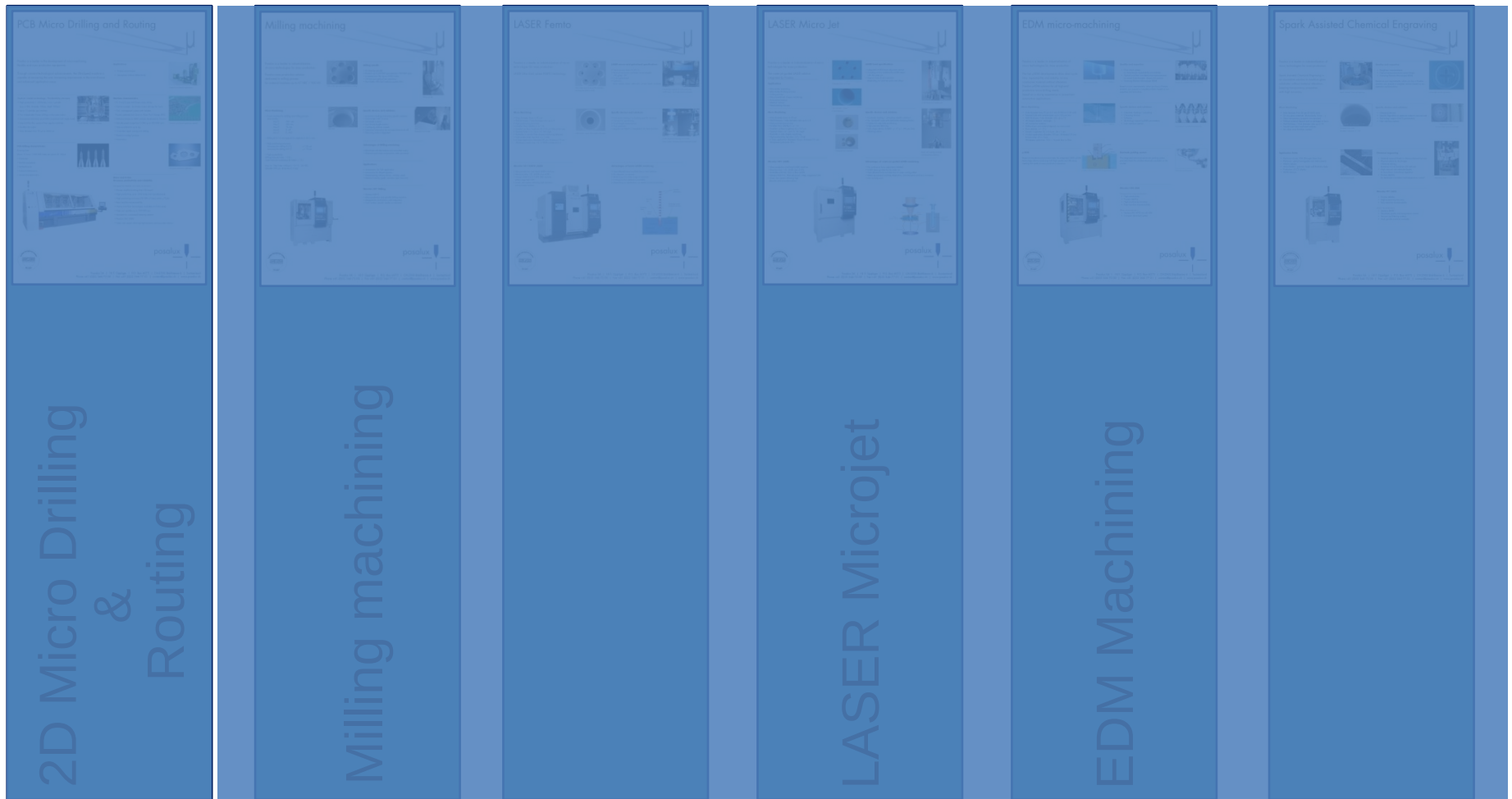
EDM Machining

Spark Assisted Chemical Engraving



S.A.C.E.

POSALUX - 6 Technologies



2D Micro drilling and routing

Specifications

- Hole diameter of 75 microns
- Hit rate: 1200 hit/min/spindle
- Accuracy +/- 25 microns
- Axes acceleration up to 4g
- Diameter/depth ratio 1/10
- 12 spindles per machine
- 12000 tools embedded



Applications

- Dedicated to non ferrous material
 - Printed circuit board (PCB)
 - Watch industry
 - Aerospace industry
- epoxy-glassfiber
→ brass
→ aluminium



2D Micro drilling and routing

Technology

- High frequency spindle 350'000 rpm
- Full linear motion
- Tool management
- Controlled depth +/- 10 microns
- SPC (Statistical Process Control)
- Tactile and intuitive MMI



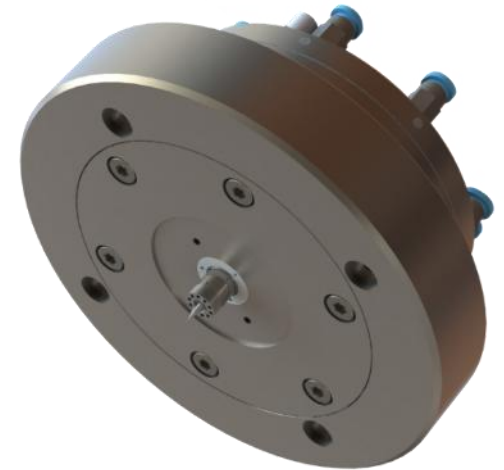
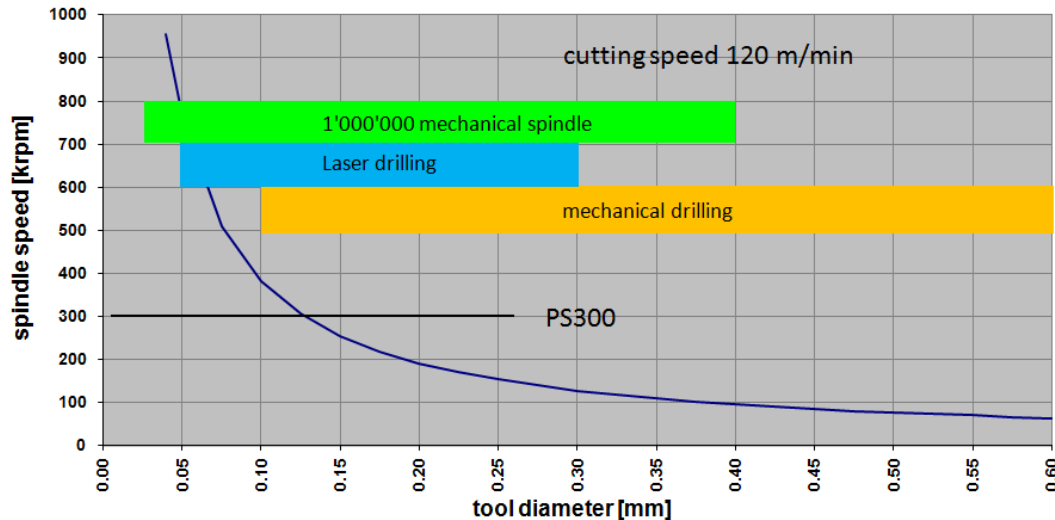
Machine configuration

- GA6000: 6 stations, 6 or 12 spindles, up to 6000 tools
- UR3600: 2 or 3 stations, 2 to 6 spindles, up to 3600 tools
- MONO: 1 station, 1 or 2 spindles, up to 2000 tools

The 1 million rpm drilling spindle

- Spindle speed : 0 - 1'000'000 rpm
- Drilling diameter range : 0 – 0.4 mm
- Clamping device: passive system without collet
- Motor: synchronous motor
- **Patented**

Spindle speed



Micro drilling-routing Mono-E

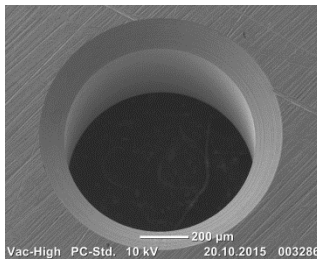
Specifications

- Tool diameter from 100 microns
- Hit rate: up to 484 hit/min/spindle
- Accuracy +/- 4 microns
- Axes acceleration up to 4g
- Diameter/depth ratio 1/10
- 2 spindles per machine
- 2000 tools embedded



Applications

- Dedicated to non ferrous material
 - ➔ Brass
 - ➔ Titanium, Aluminum
- Watch industry
- Medical



High precise drilling-routing Mono-E

Technology

- High frequency spindle 200'000 rpm
- High stiffness routing spindle 60'000 rpm
- Full linear motion
- Tool management
- Controlled depth +/- 10 microns
- SPC (Statistical Process Control)
- Tactile and intuitive MMI



Machine configuration

- MONO: 1 station, 2 spindles, up to 2000 tools
- Automation: individual loader with 8 stacks

POSALUX - 6 Technologies



Micro Milling

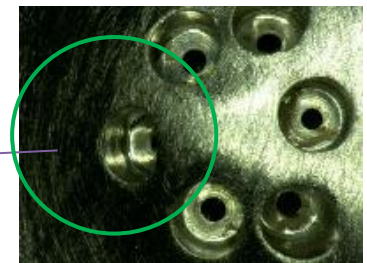
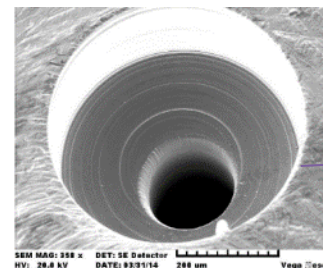
Specifications

- Micro Milling for hardened material < 67 HRC dia.0.3 to 0.6 mm
- High productivity (6 step-hole and 2 marks < 13 sec)
- Vibration reduction during milling process
- Cutting force optimised
- Tool life optimised
- Dedicated to customer application



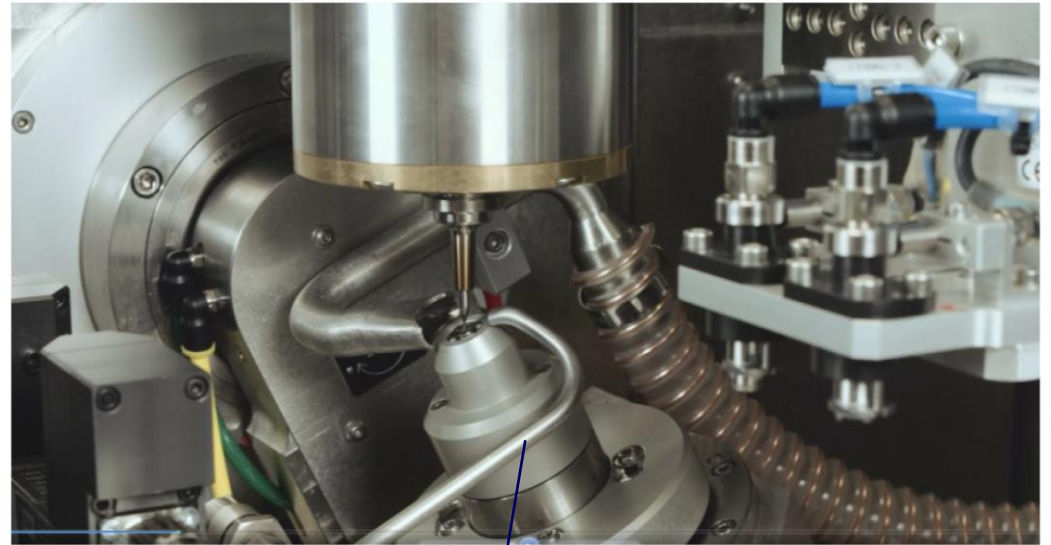
Applications

- Dedicated to hardened ferrous material
- Stainless steel
- Titanium
- Automotive and Medical

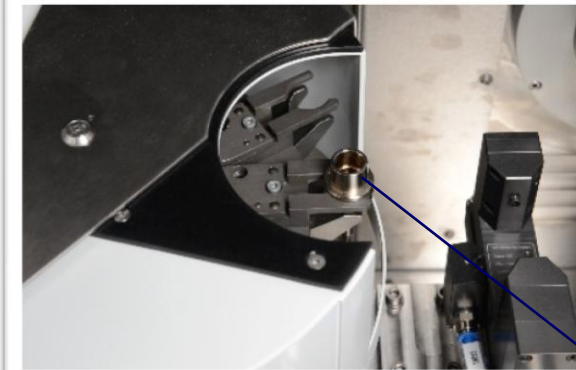


Micro Milling

Tool Changer
(12 positions)



Complete Milling process



100% Laser checking of tools

POSALUX - 6 Technologies



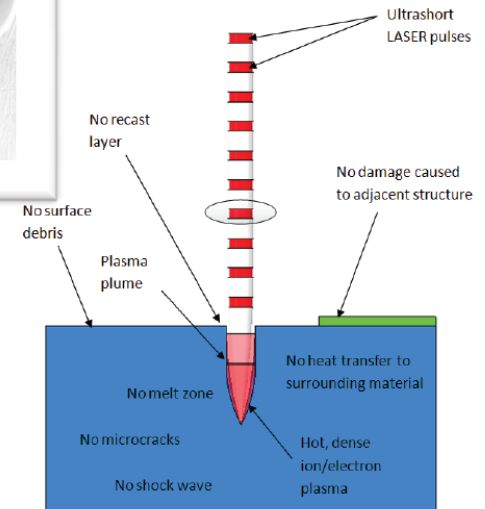
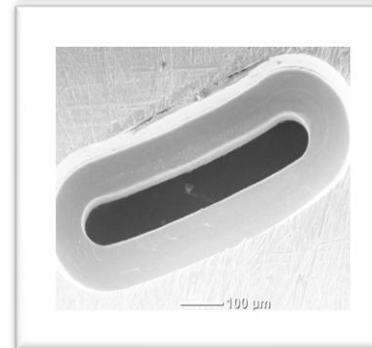
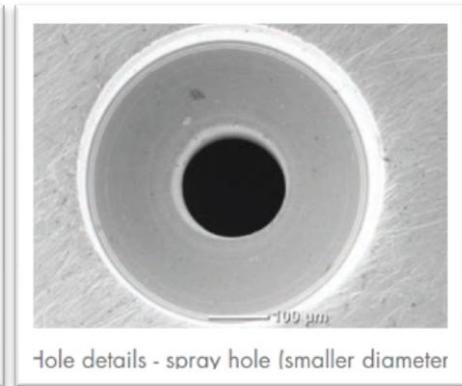
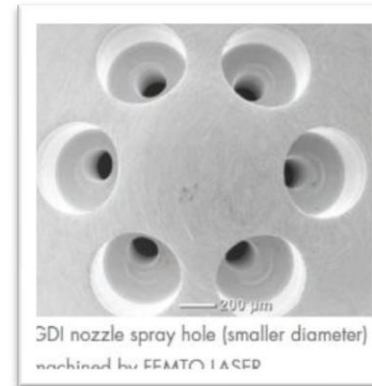
Micro drilling and cutting with FEMTO Laser

Micro Machining

- Hole diameter down to 90 μm
- Wall thickness / hole diameter ratio up to 10
- High positioning accuracy
- High productivity: less than 1,4s / hole
- Excellent flow stability in +/- 1%
- Excellent surface roughness R_a 0.05 μm (like polished)
- Tapered holes + 23° or - 15° full angle
- Flexibility in circular hole shapes machining (ellipses)

Advantages of FEMTO Laser machining

- Heat affected zone avoided due to cold ablation
- No deposits, no recasts
- Machining of a wide range of materials
- Cutting function (ablation) available
- Depending on application: no needs of amount process



Micro drilling and cutting with FEMTO Laser

LASER source and galvohead specifications

- Femto source down from 230 fs to 10 ps
- Various harmonics available (wave length): nIR, Green, UV
- 5 axis galvohead
- Optional: Vision system, Beam focus analyser
- Pulse energy up to 200 μ J (10W)
- Pulse frequency: 1 Hz – 2 MHz

Specific devices and solutions

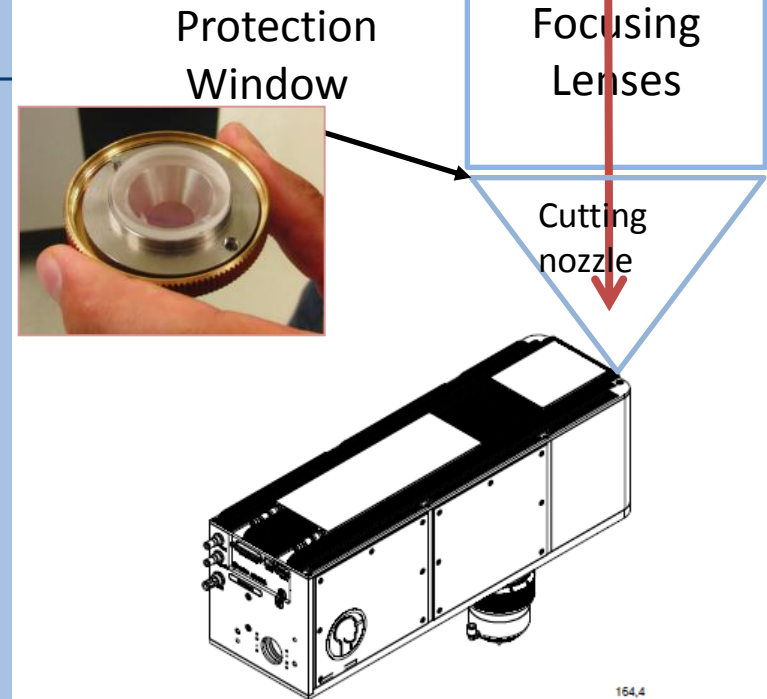
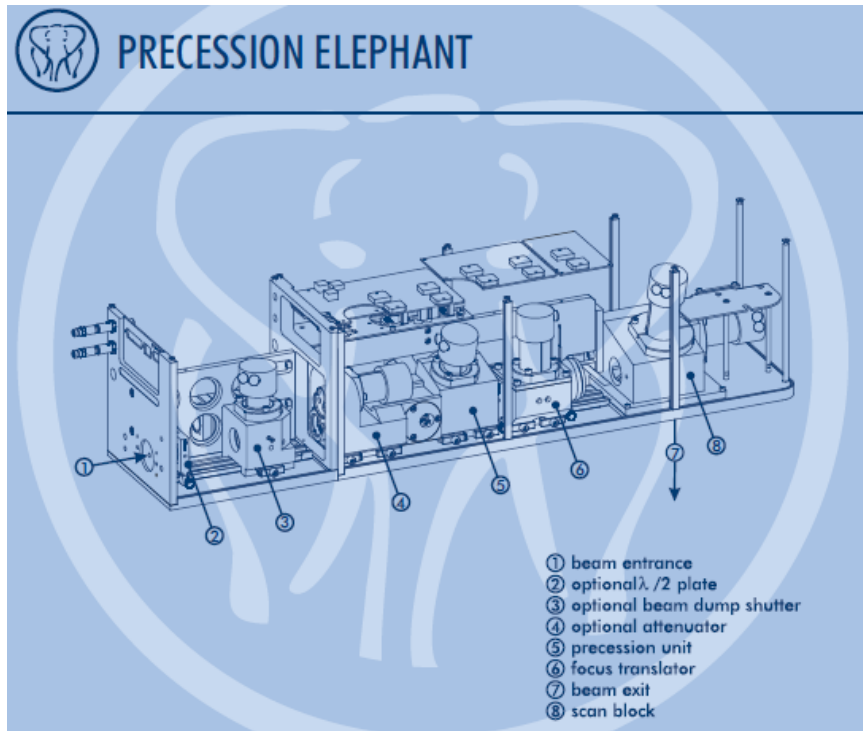
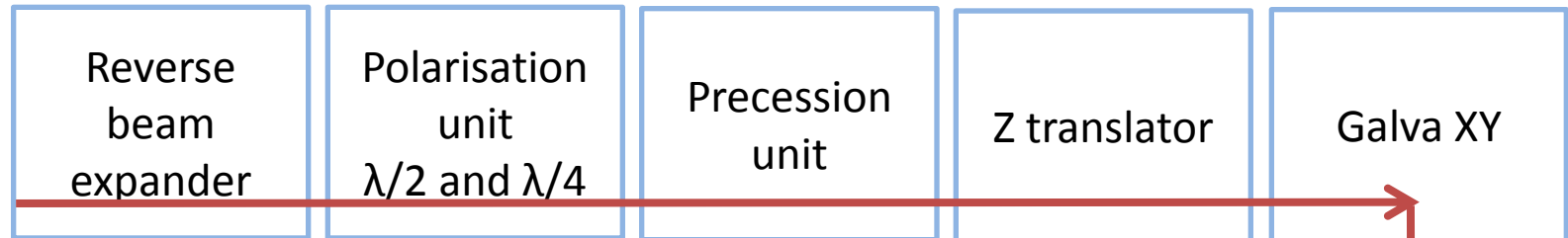
- Automatic loading / unloading specific solutions
- Camera for step hole positioning
- Focal length measurement
- Dust extraction

Microfor HP1 FEMTO LASER

- Mass production one head LASER machine
- Machine class 1 (I), LASER class 4 (IV)
- Siemens 840 D sl 4.5 SP2 HMI operate, safety integrated CNC
- Linear axis system allowing high
- Dynamic and accurate motions



Arges Drilling Head – Elephant 3D



Trepaning with Arges Head

PERFORMANCE

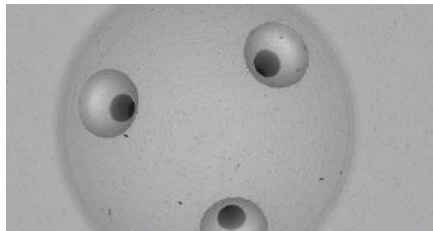
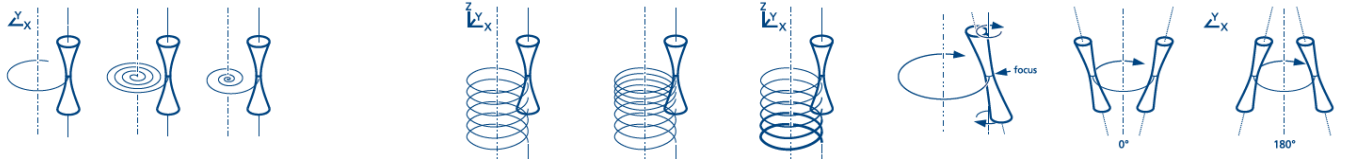
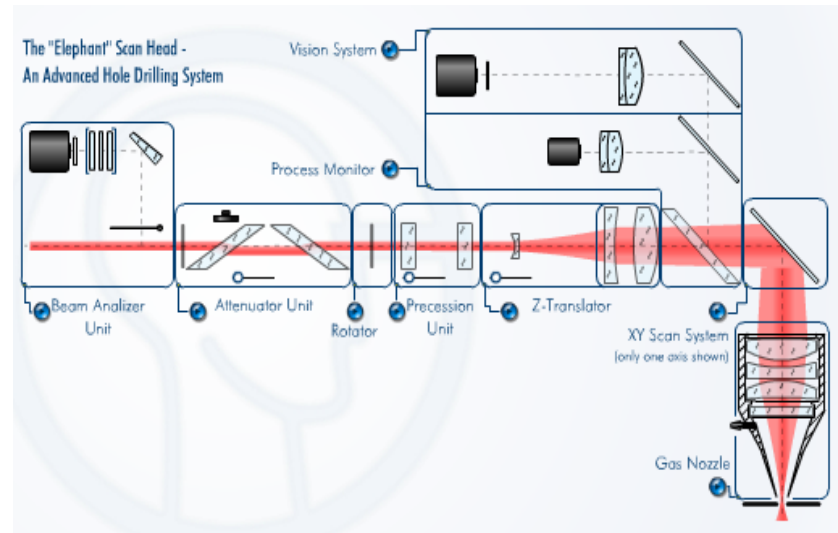
DRILL PARAMETER	TYPICAL VALUE
Hole Diameter Range ¹	50 µm-500 µm
Material Thickness ^{1,2}	~ 1 mm
Cycle Time ³	~ 2 seconds/hole
Taper Angle Range ¹ (full angle)	Pos. & neg. to 10°
Hole Circularity	> 95 %
Surface Quality (inside wall)	$R_a < 0.1 \mu\text{m}$
Diameter Resolution	< 1 µm
Diameter Repeatability	< 0.4 %
Hole Position Accuracy ⁴	$\pm 1 \mu\text{m}$

¹⁾ Please inquire regarding features outside this range.

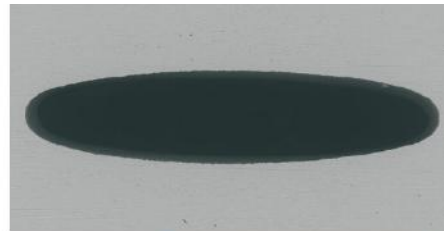
²⁾ Maximum material thickness is dependent on hole dimension.

³⁾ Cycle time quoted for 200 µm diameter hole in 200 µm thick 440 stainless steel.

⁴⁾ Hole position repeatability is dependent on overall workstation design and quality.



2 mm



200 µm



300 µm

Watchmaking Applications

Potential applications

- Texturations, engraving, cutting, ...
- Silicon, ceramic, glass, sapphire , steels, precious stones,
- All shapes for watchmaking...

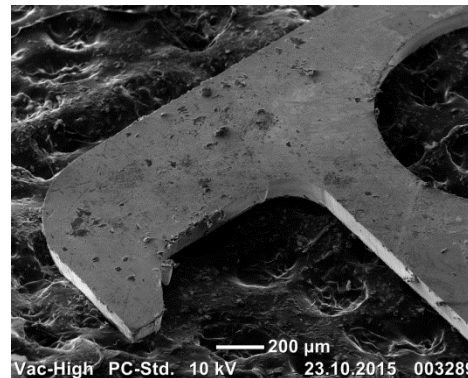
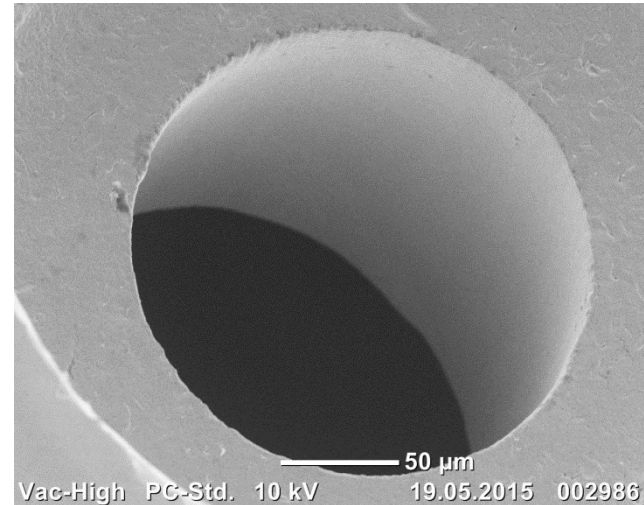
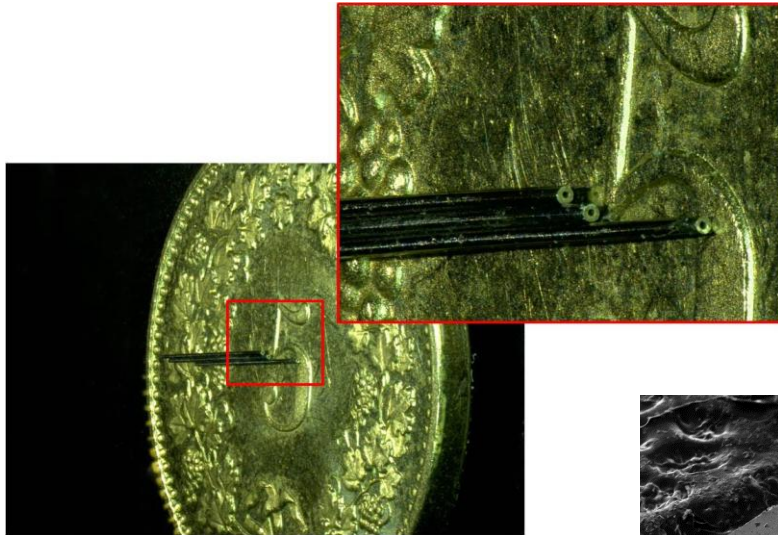


Femto: Challenges Posalux durant les 12 derniers mois

- Circularité → $< 1.5 \mu\text{m}$ ✓
- Cylindricité / Rectitude → $< 1.5 \mu\text{m}$ / pour tous ratio ✓
- Formes entrées / sorties → angle vif, contrôle rayon ✓
- Cônes positifs → jusqu'à $+ 23^\circ$ ✓
- Cônes négatifs → jusqu'à $- 15^\circ$ ✓
- État de surface → $< 50 \text{ nm}$ ✓
- Ratio dia/prof → 1:13 (e.g. $30 \mu\text{m}$ / $400 \mu\text{m}$) ✓

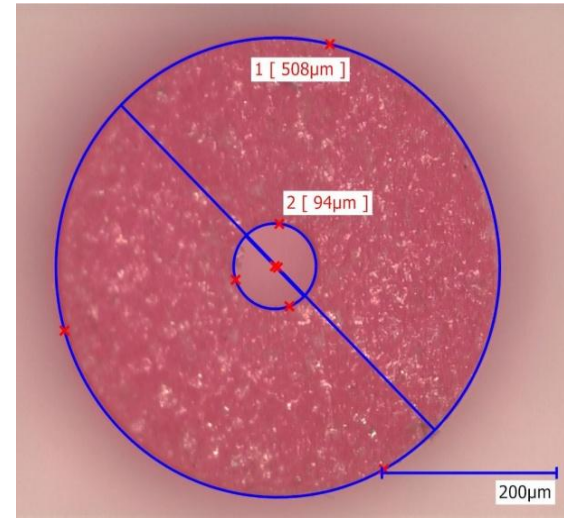
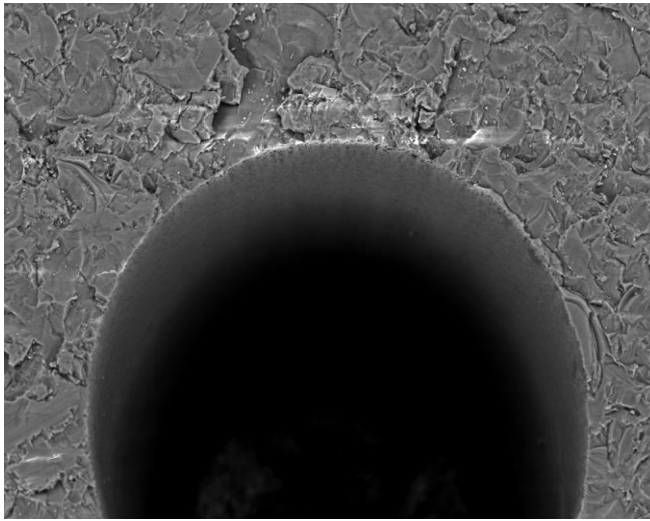
Matériaux - validés, expérimentés, testés

➤ Aciers d'améliorations, faiblement alliés, inoxydables, trempés et non trempés, les laiton



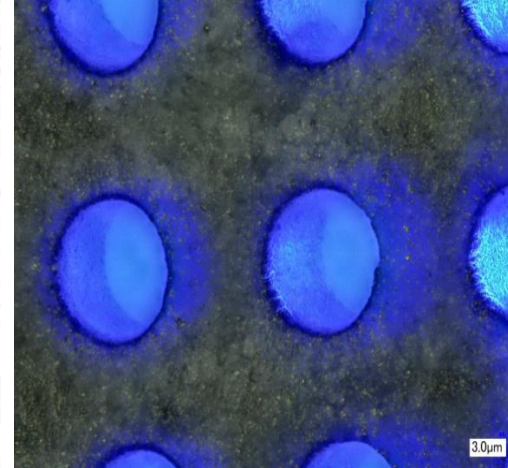
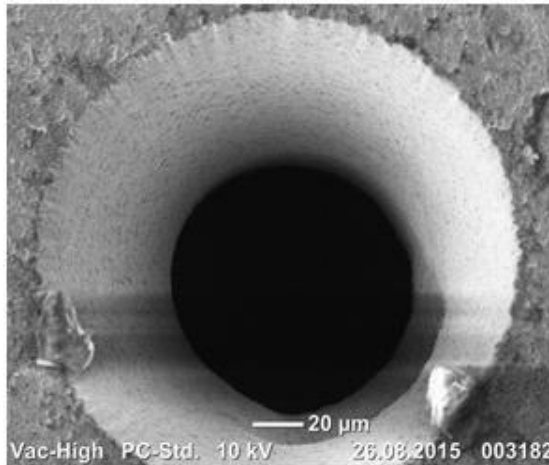
Matériaux - validés, expérimentés, testés

➤ Rubis



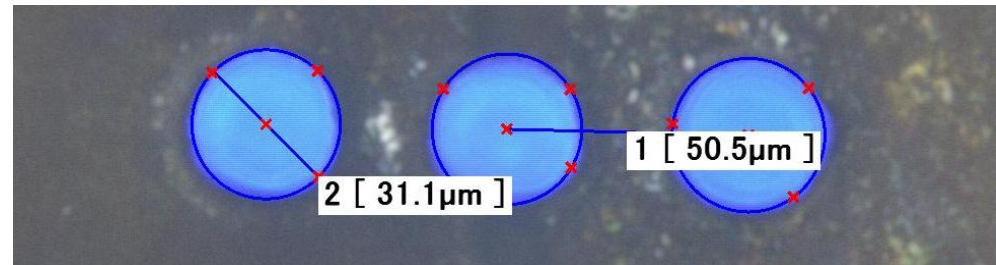
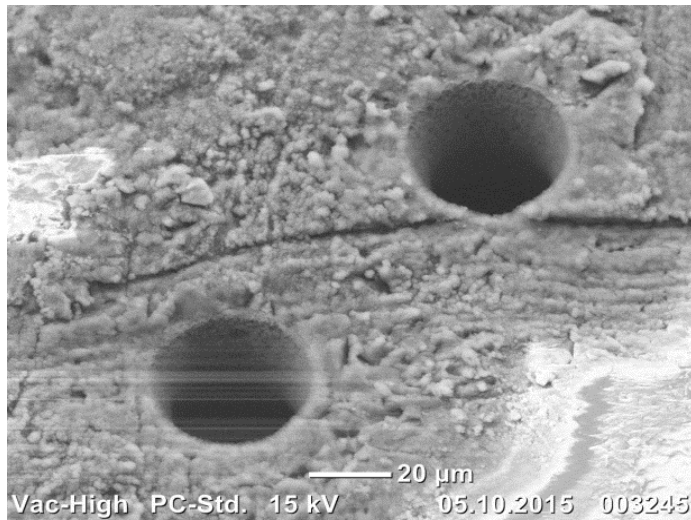
Matériaux - validés, expérimentés, testés,

➤ Céramiques



Matériaux - validés, expérimentés, testés,

➤ Polymères (Peek)

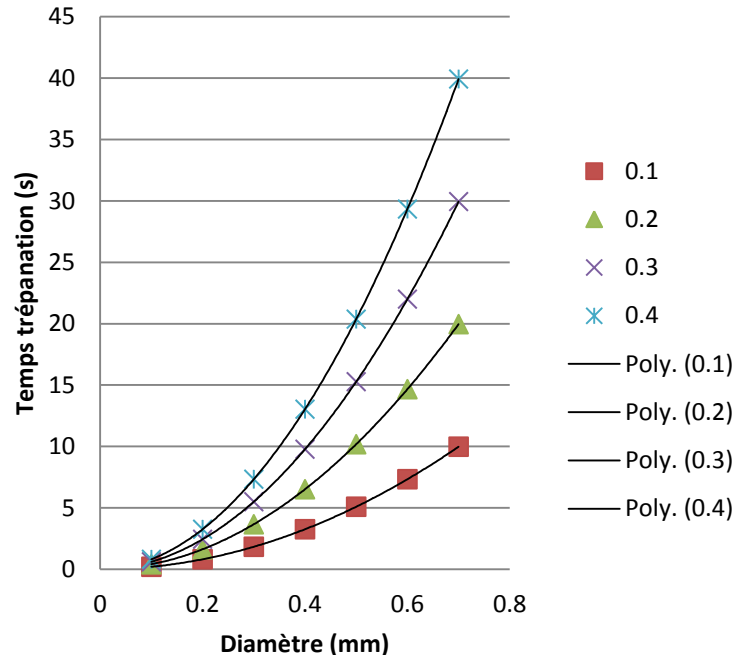


Matériaux – à valider par Posalux

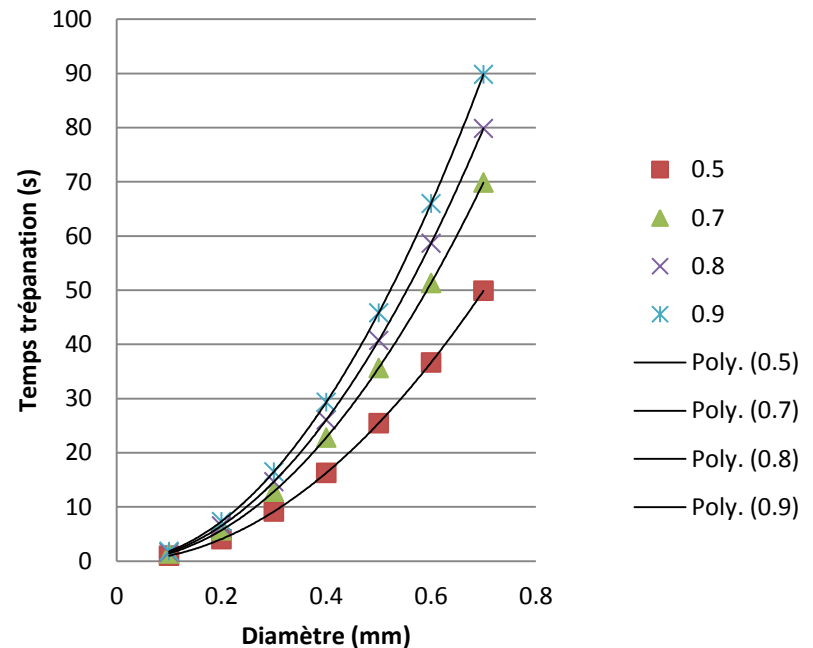
- Nitrure d'Aluminium *(en cours)*
- « Usinage » de revêtements *(en cours)*
- Verre et Silicium
- Saphir
- Autres Polymères, PMMA (plexiglas)
- Matériaux précieux

Usinage - perçage

**Temps laser suivant Prof.
matière-petite épaisseur**



**Temps laser suivant Prof.
matière-grande épaisseur**

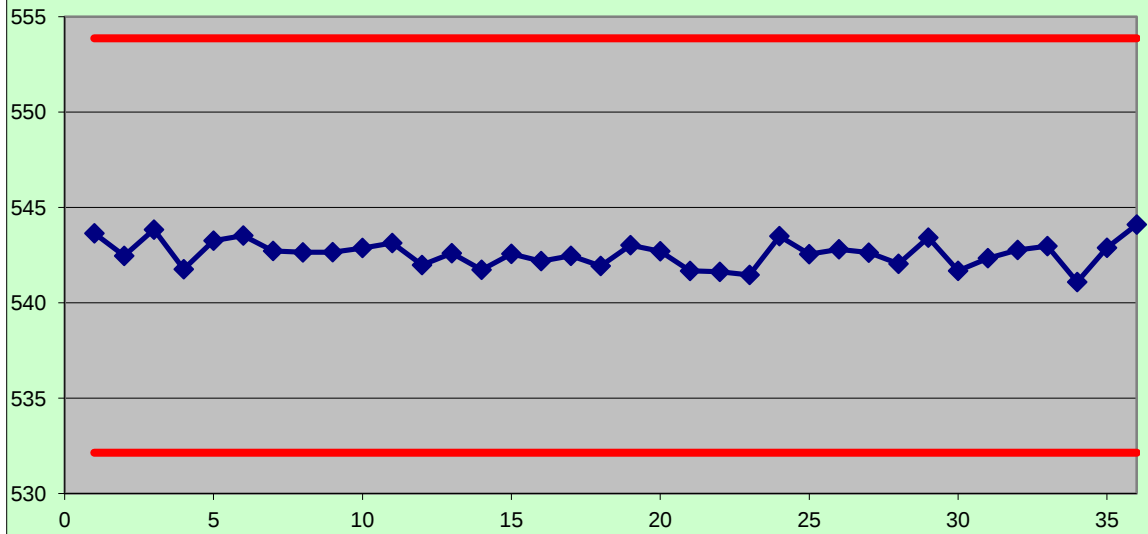


Aciers trempés > 750 Hv / Trou $\varnothing 200\mu\text{m}$ / Longueur $300\mu\text{m}$
Tolérances $1\mu\text{m}$

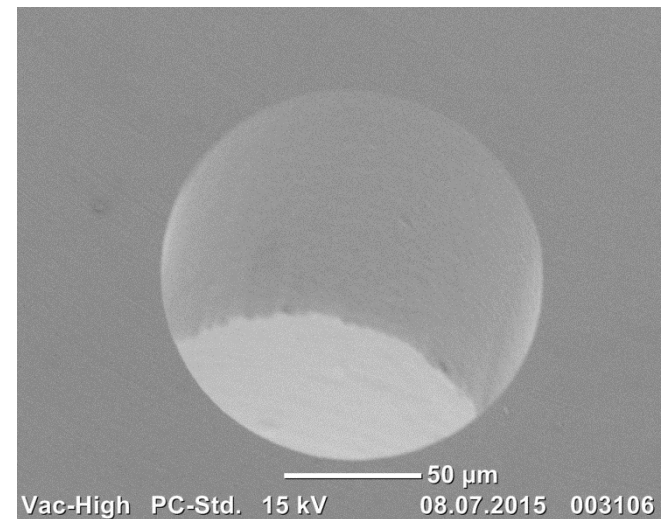
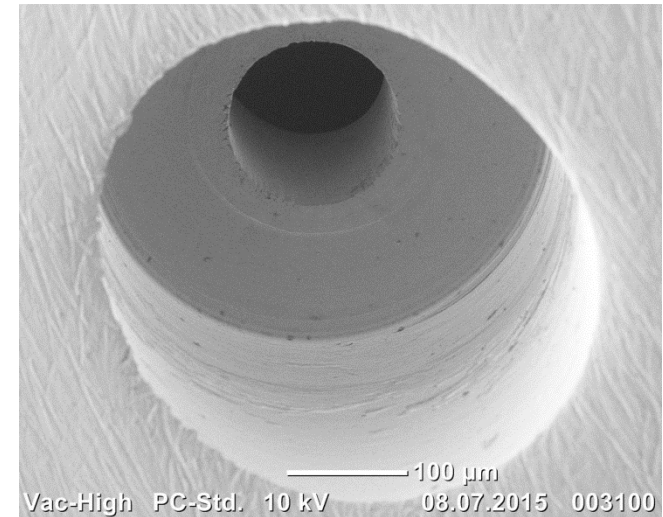
➔ Temps de perçage = 1,4 Sec

Usinage - perçage dia. 141 μm

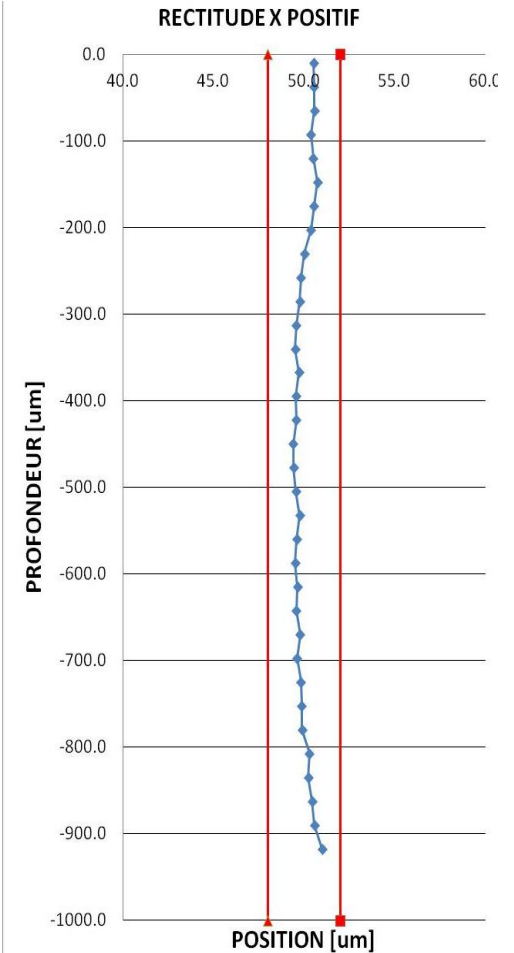
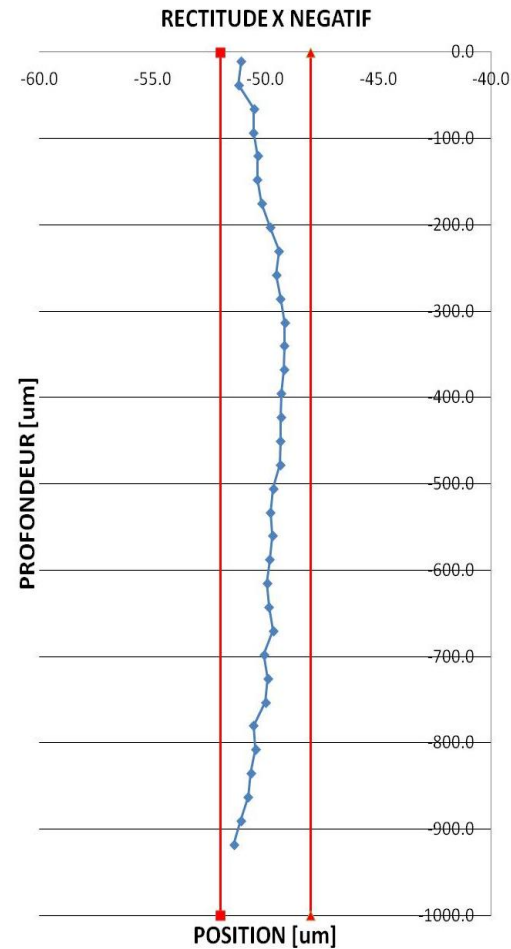
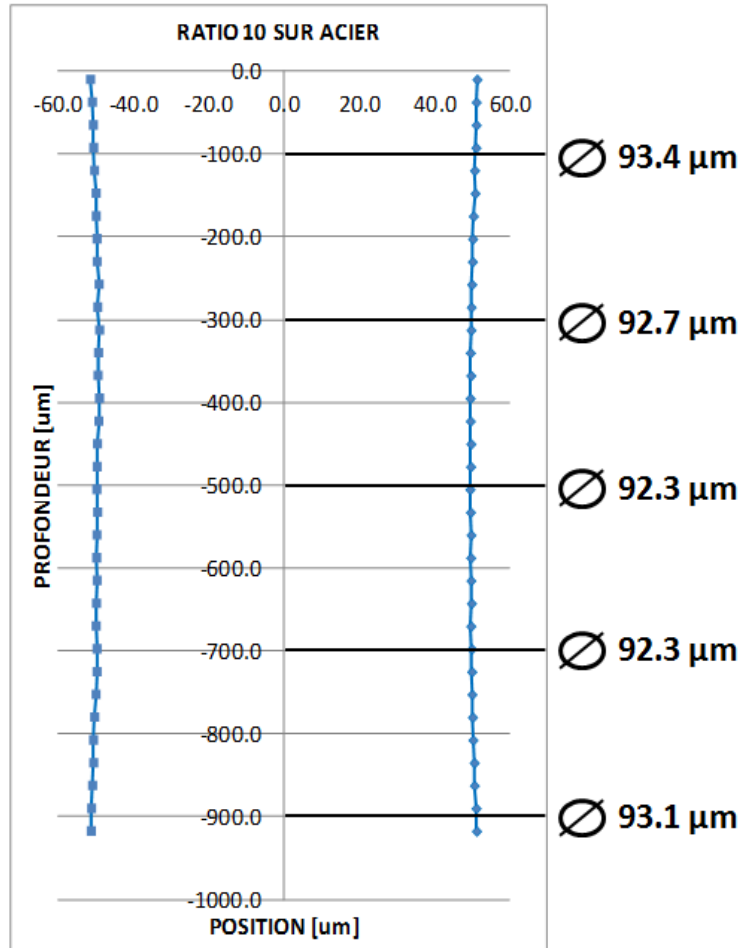
Mesure de débit avec tolérance +/- 2 %



Cp	5.10
Cpk	4.91

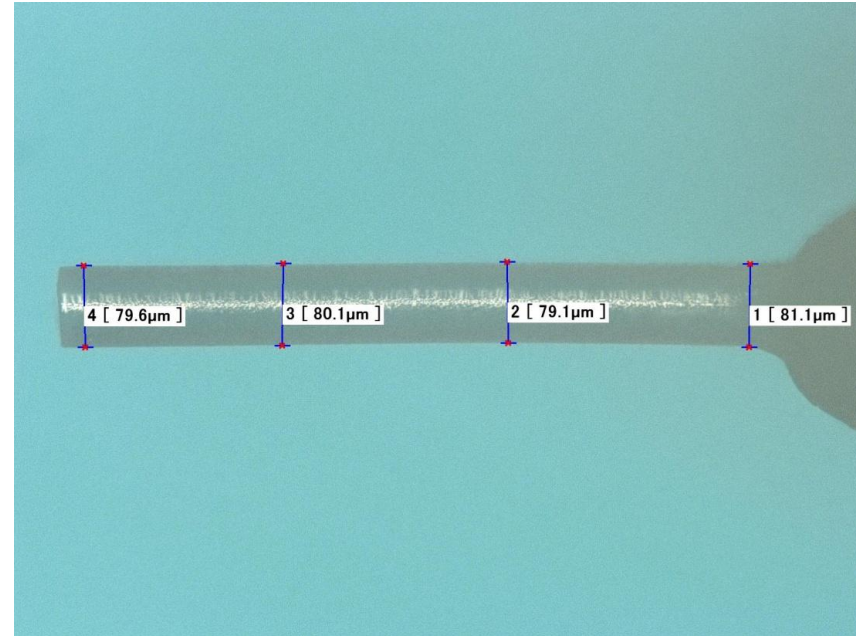


Perçage – Ratio 10 sur acier

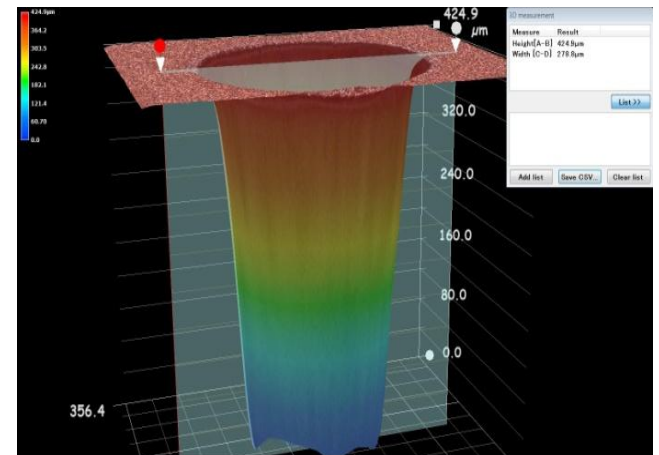
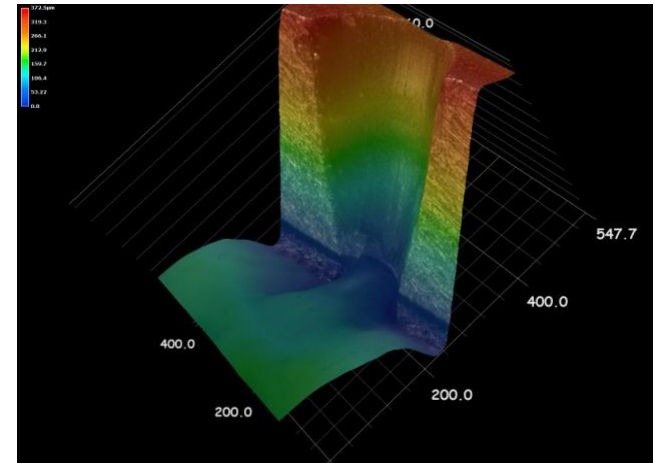
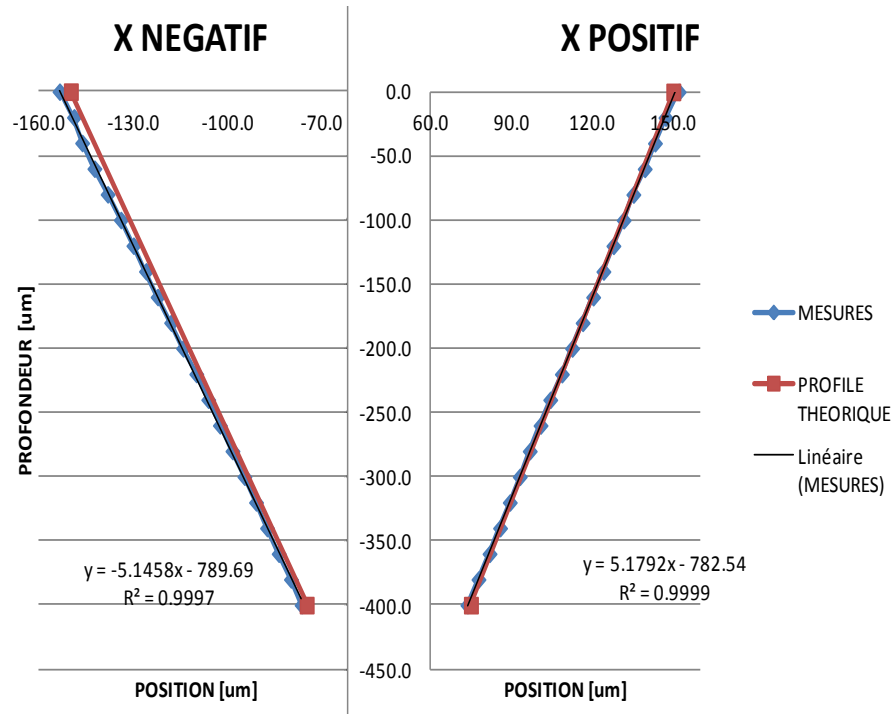


Usinage - perçage

- Trou profond diamètre 80 μm / 800 μm
- Aciers Ratio 1:10
- Peek Ratio 1:13

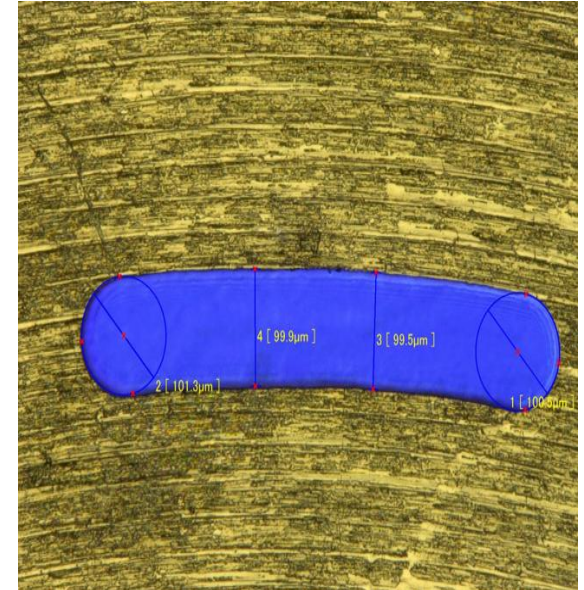
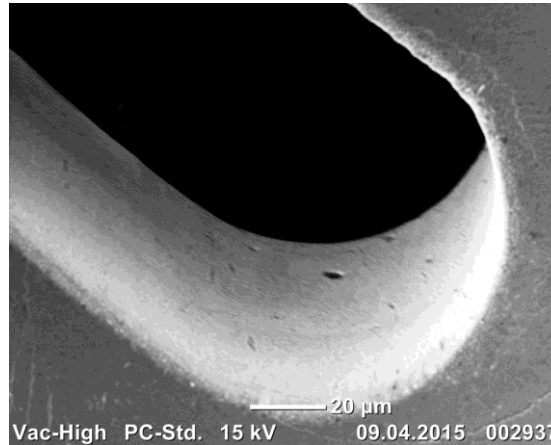
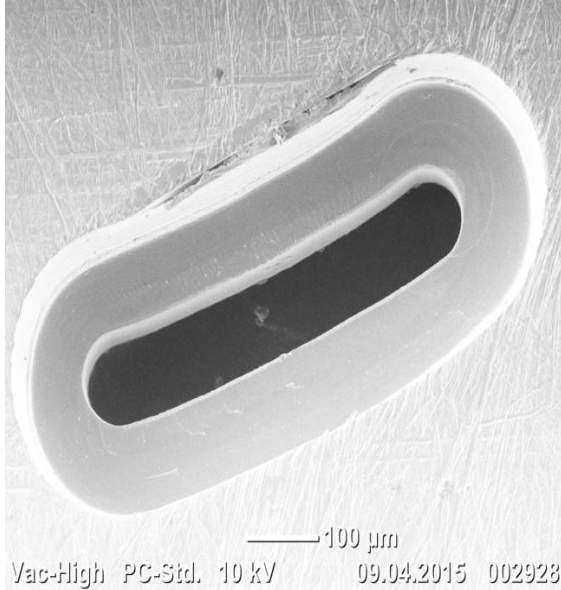


Usinage -Perçage cône +23 ° sur acier

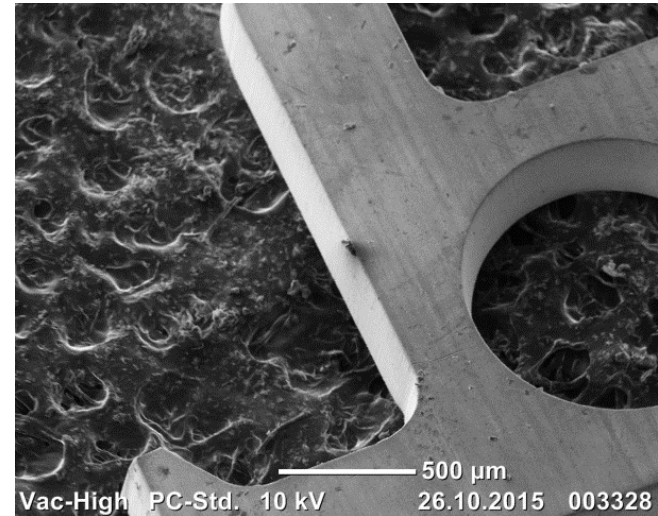
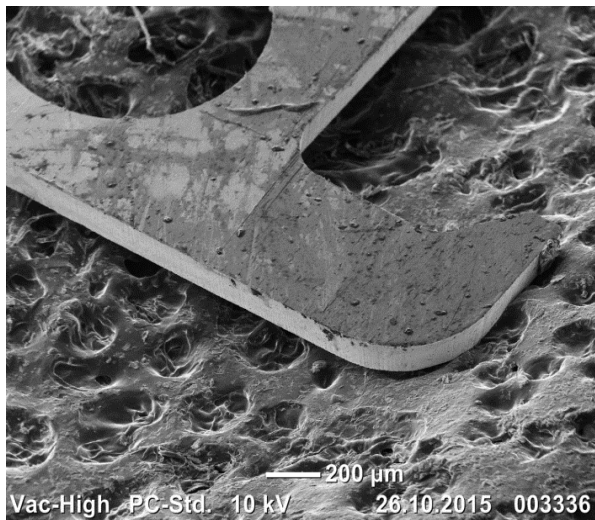


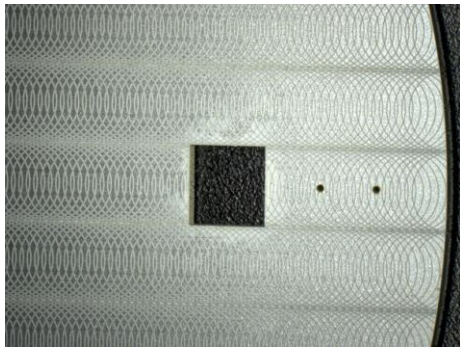
Pour info : Cône négatif -15° atteint

Usinage - découpe forme oblong

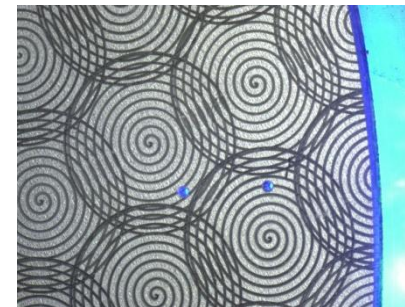
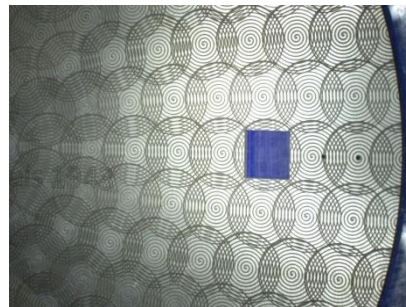
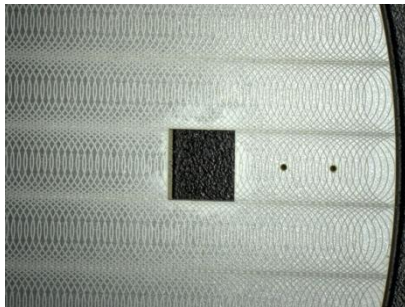
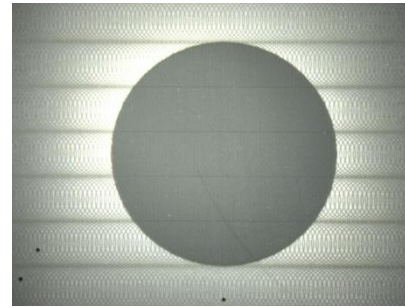
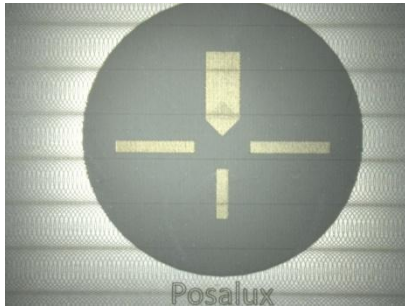


Usinage - découpe exemples





Usinage – gravage / texturation



Matière :

Alu

Epaisseur :

0.3mm

Dépouille :

[20;30]µm

Tolérance de forme :

<30µm

Temps de cycle :

>10-12min

(Via 515nm)

Etat de surface :

Ra<0.2

Opérations :

- 1) Texturation
(Cote G et perlage)
- 2) Marquage (Px et évidement)
- 3) Gravage Px
- 4) Percage
- 5) Découpe

Concept Femto Mono Combi

Concept perçage, découpe et scanning

Une source Laser alimentation une tête optique Combi mode :

1 source Laser

1 head switch précis pour commuter sur les 2 chemins optiques

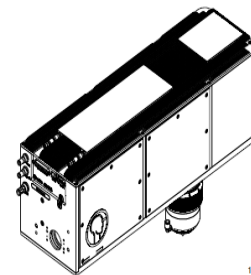
2 optiques d'usinage.

5 axes 3D avec système de precession pour la réalisation les opérations de perçages avec formes possibles cylindriques ou coniques positifs ou négatifs.

3 D permettant de réaliser les opérations de scanning sur pièces convexe/concave

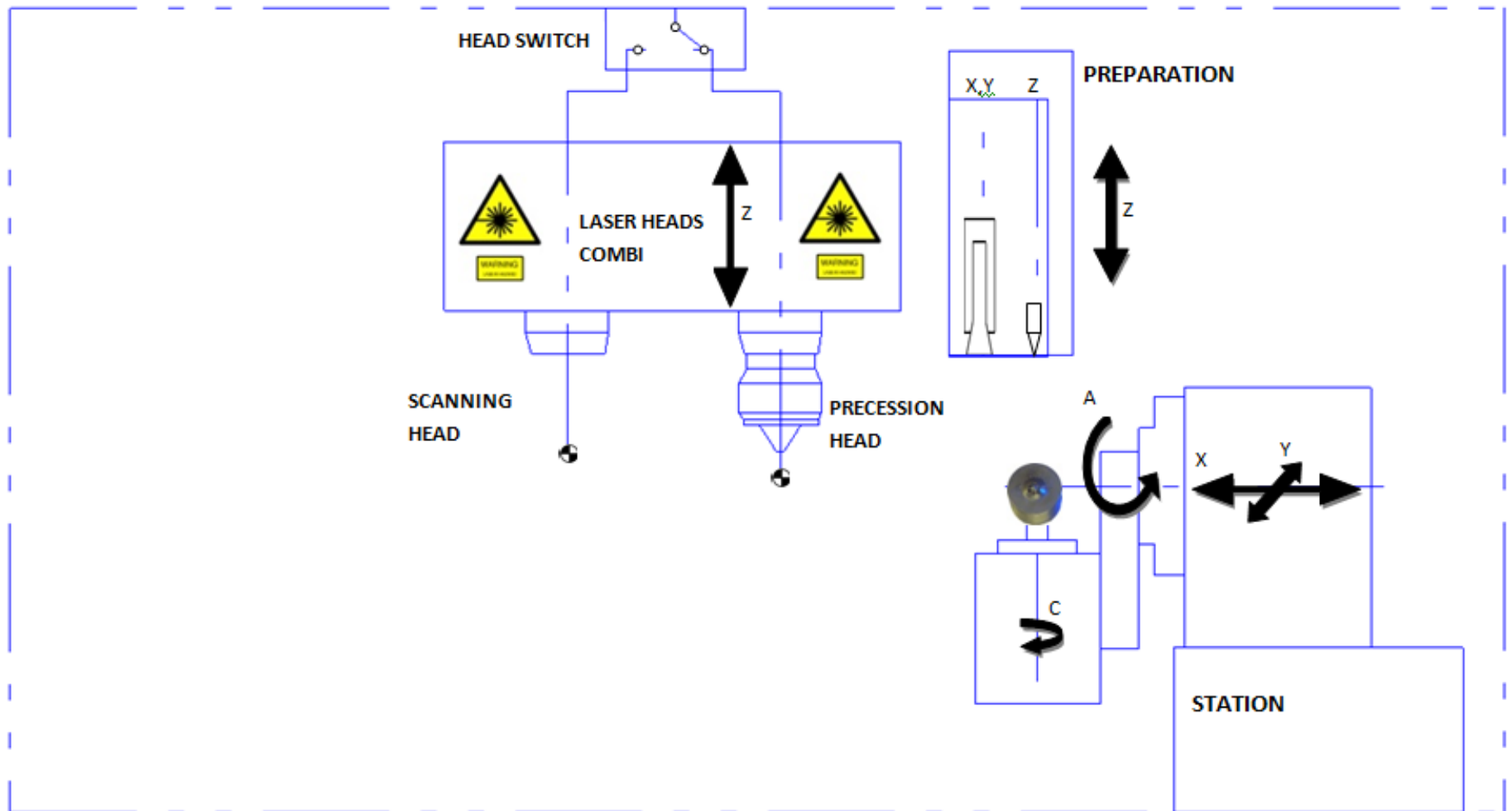


Femto Mono Combi



Optical Elephant head Combi (drilling/cutting + scanning mode)

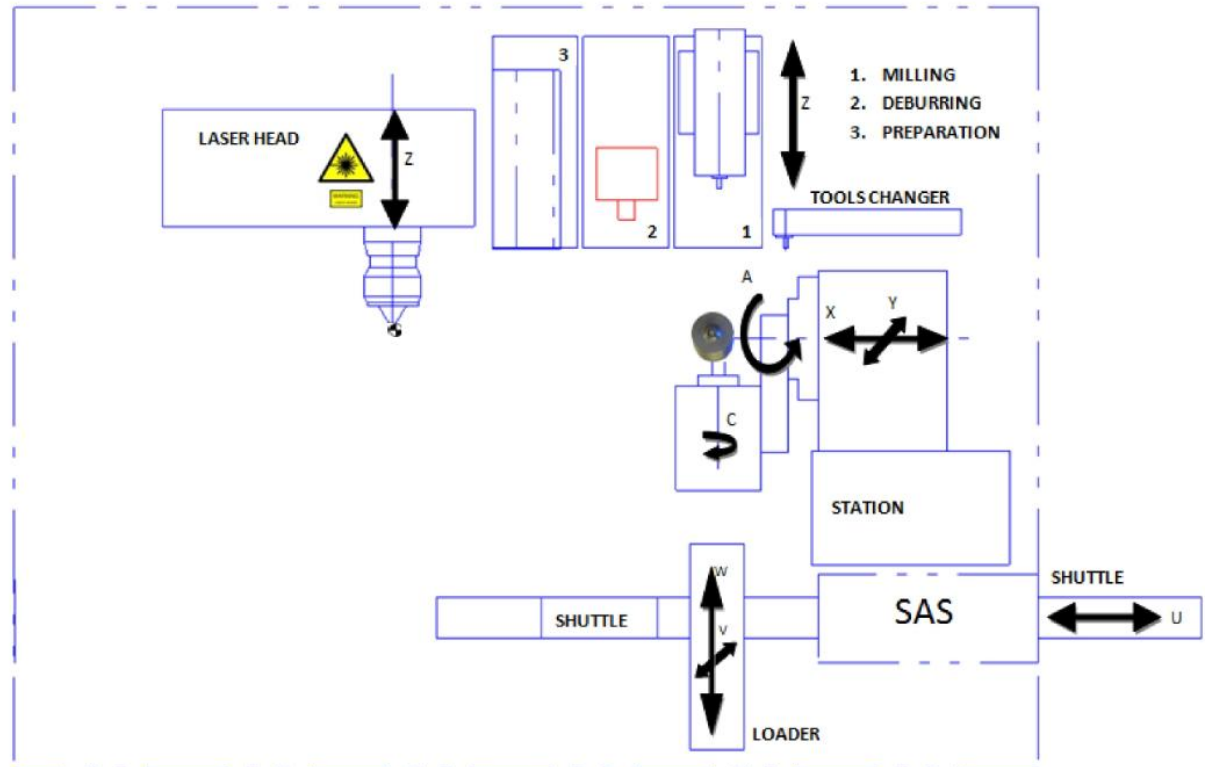
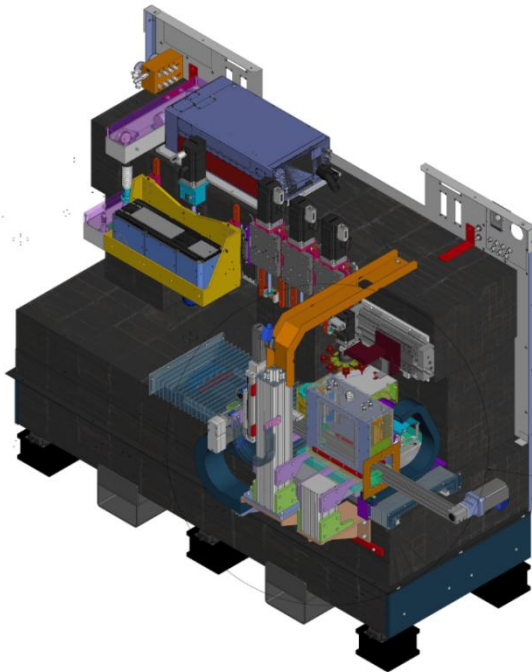
Concept de base Femto Mono Combi



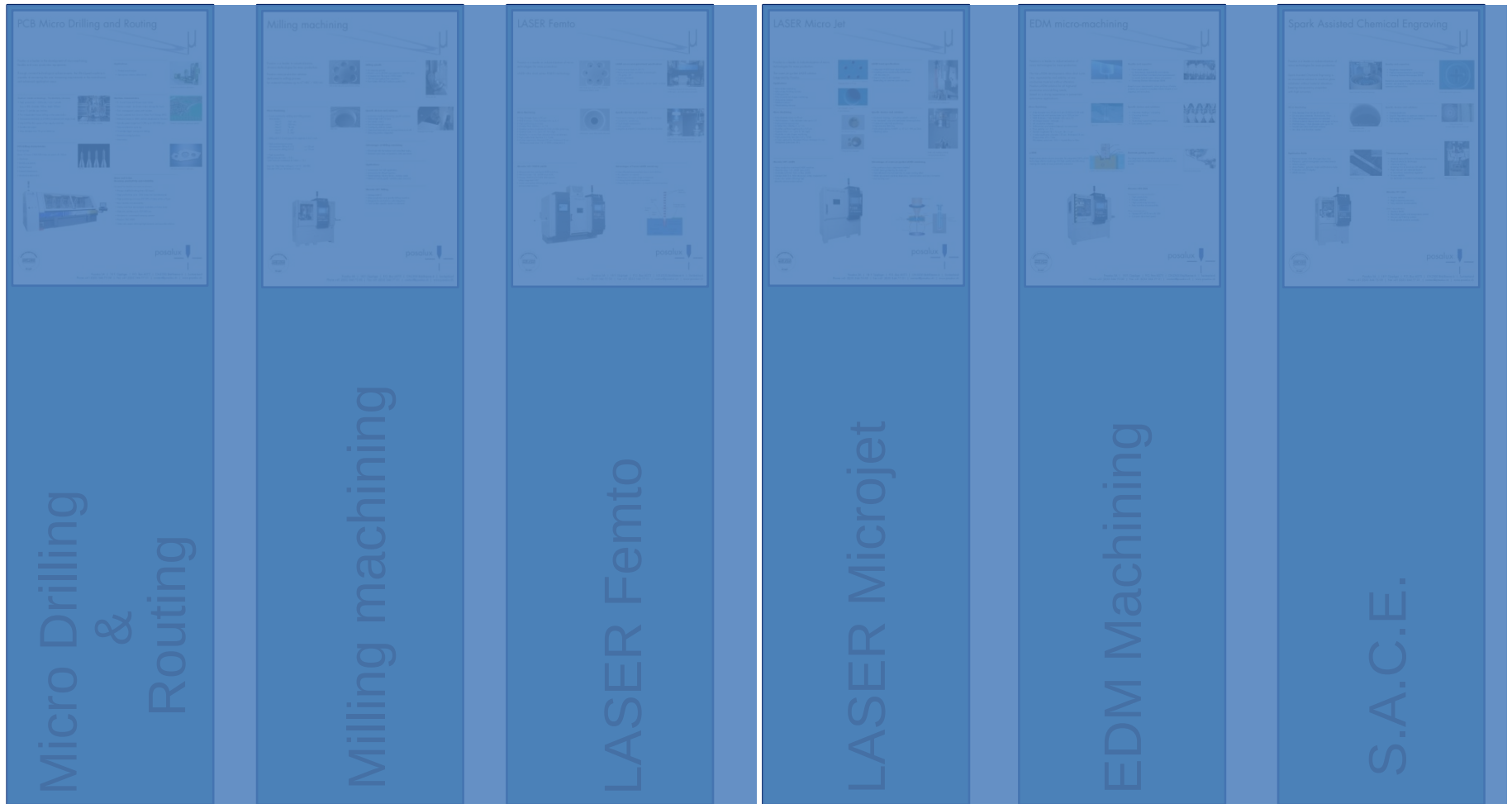
Concept Femto Mono Combi 2

Concept Milling, Deburring and Drilling

MICROFOR HP1 FEMTO LASER MONO COMBI



POSALUX - 6 Technologies



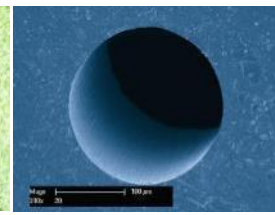
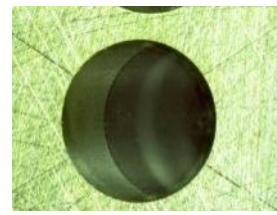
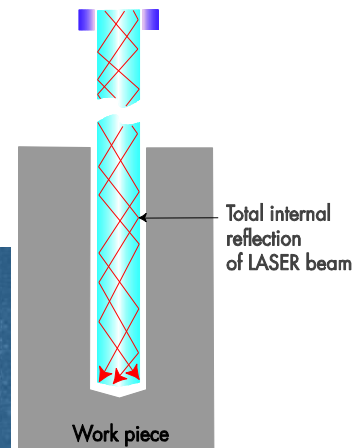
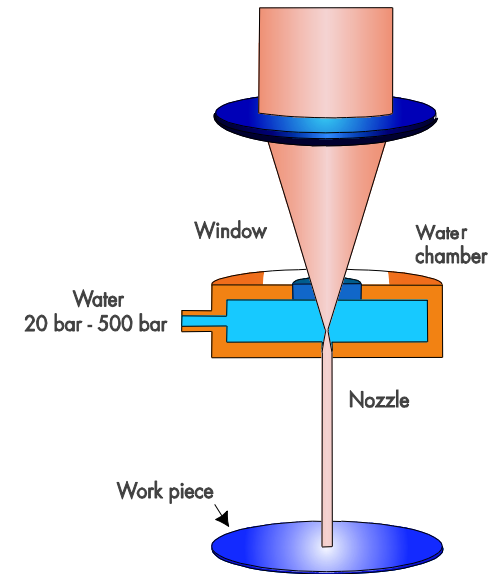
Micro drilling and cutting with LASER Micro Jet

Micro Machining

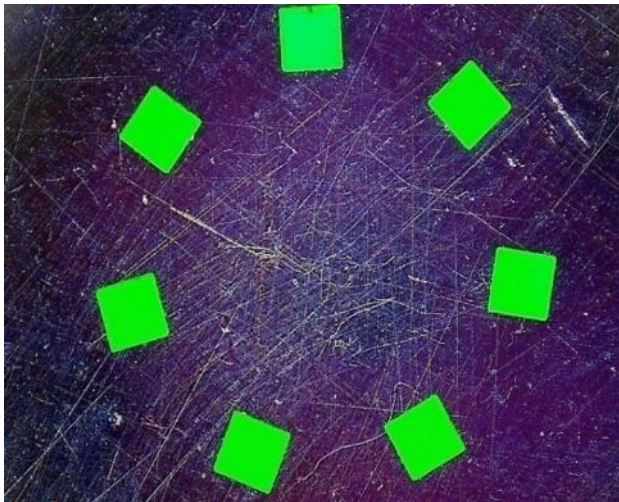
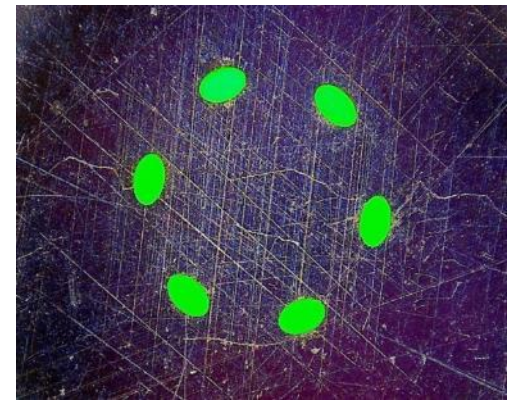
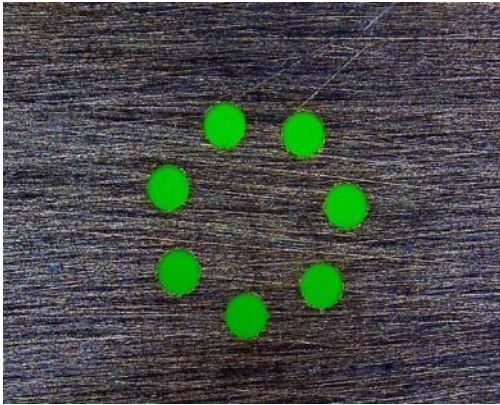
- Hole diameter down to 90 μm
- Wall thickness / hole diameter ratio up to 3.5
- High positioning accuracy
- High productivity: less than 2s / hole (dia.150 μm)
- Excellent flow stability in +/- 1%
- Excellent surface roughness $R_a < 0.5 \mu\text{m}$
- Tapered holes + or - up to 6° full angle
- Flexibility in hole shapes machining

Applications

- Dedicated to ferrous or no ferrous material
- Automotive industry: Gasoline Direct Injection
- Watchmaking Industry: cutting and finishing holes (steel, silicon,)



LMJ – various holes and shapes possible



Micro drilling and cutting with LASER Micro Jet

LASER head specifications

- Integrated LASER beam alignment device
- Coupling unit to combine the LASER beam with the water jet
- Vapors fume & dust extraction depending on customer parts and alloys
- Head with coupling unit (top) Clamping fixture (bottom)

Specific devices and solutions

- Automatic loading / unloading specific solutions
- No 'backwall' issue with dedicated clamping fixture
- Camera for step hole positioning
- High pressure deburring
- Hole shape device "A-AXIS" $\pm 3^\circ$ ($\pm 100 \mu\text{m}/\text{mm}$)
- Washing station

Microfor HP1 LASER

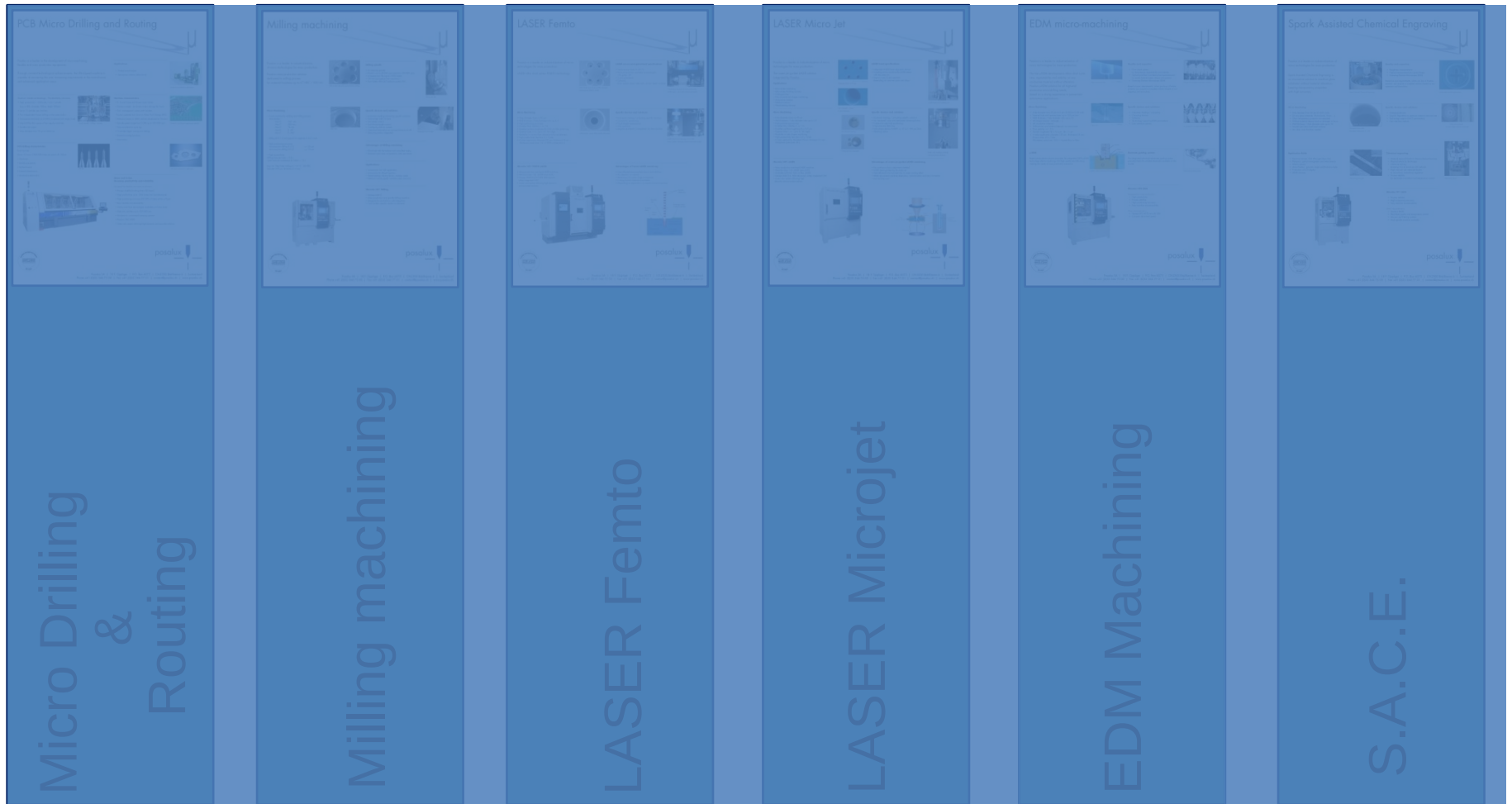
- Mass production one head LASER machine
- Machine class 1 (I), LASER class 4 (IV)
- Available with Nd YAG or fiber LASER
- Siemens 840 D sl, HMI advanced, safety integrated CNC
- Linear axis system allowing high dynamic and accurate motions



Head with coupling unit (top)
Clamping fixture (bottom)



POSALUX - 6 Technologies



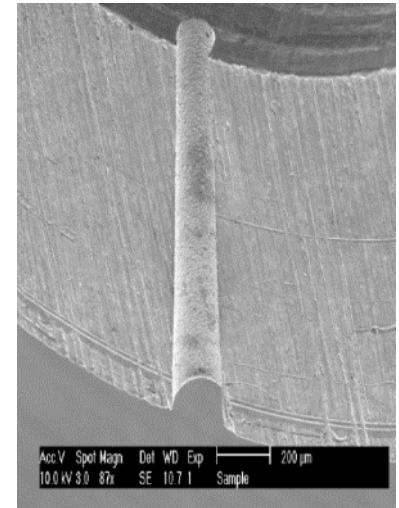
Micro drilling with EDM

Specifications

- Hole diameter of 50 microns
- Accuracy +/- 3 microns
- Diameter/depth ratio 1/12
- 4 spindles per machine
- Conical hole

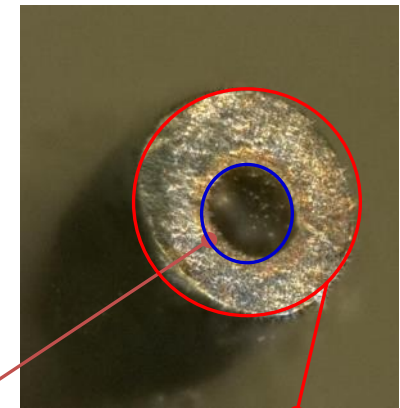


Ø 50 µm



Applications

- Dedicated to conductive material
- Automotive industry :
 - Diesel high pressure
 - Gasoline Direct Injection (GDI)
- Medical :
 - Needle



hole Ø 60 µm

needle Ø 150 µm

Micro drilling with EDM

Technology

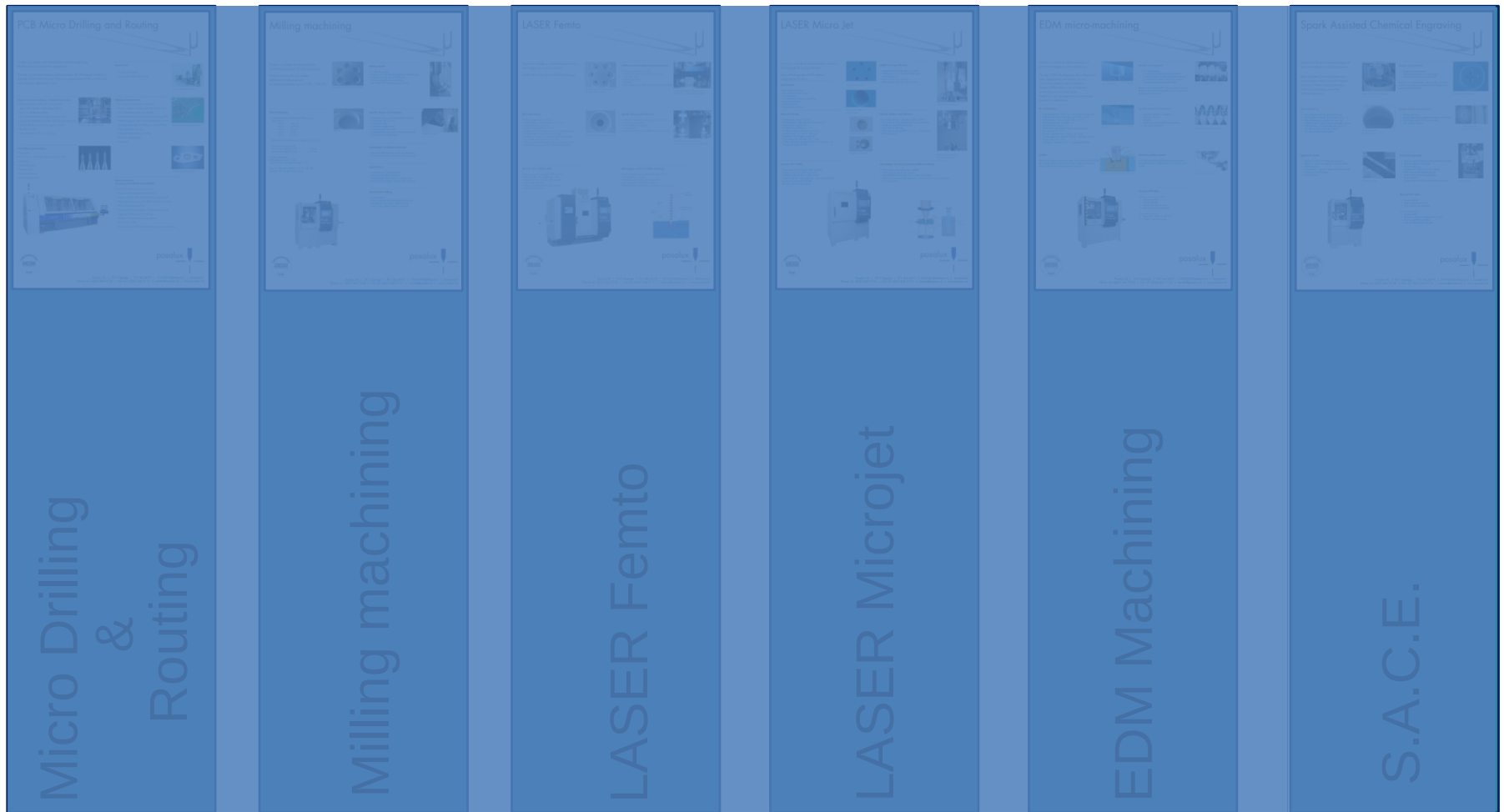
- Short pulse SARIX generator (80 nano secondes)
- Regulation by average voltage
- 6 axes machine

Machine configuration

- HP4: 1, 2 or 4 spindles
- Available options → Automatic load/unload of parts
→ Flow control



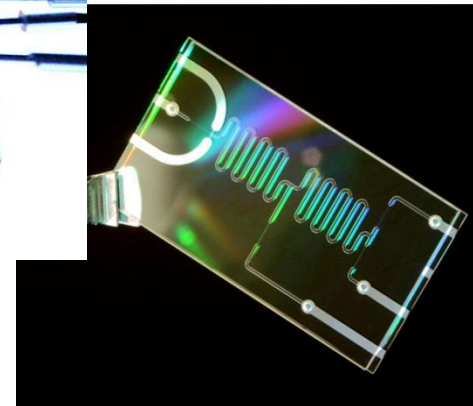
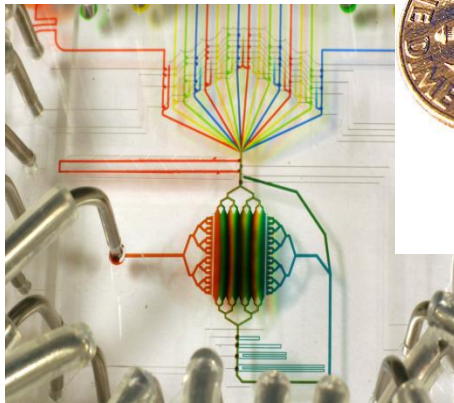
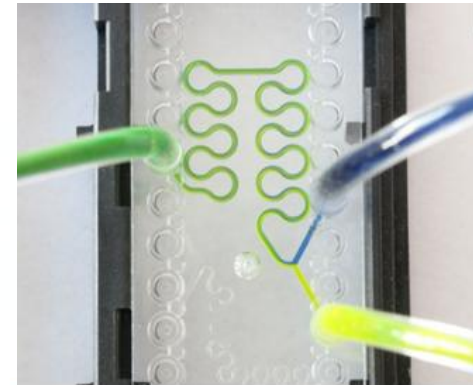
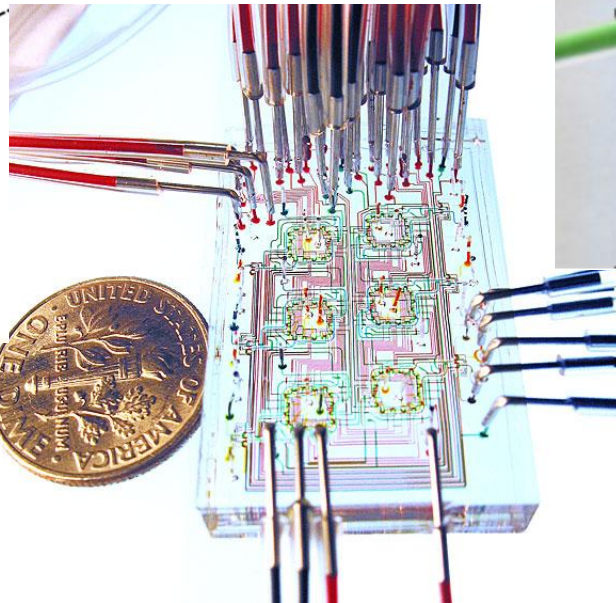
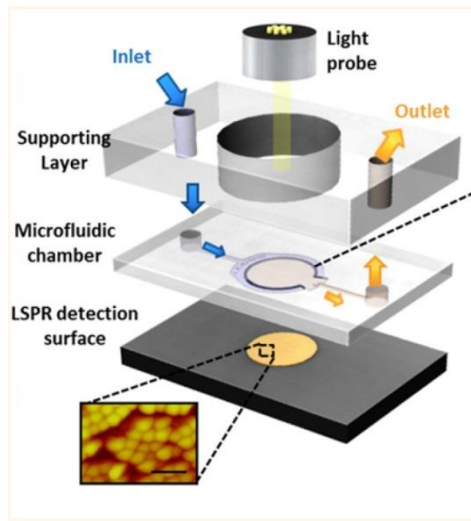
POSALUX - 6 Technologies



Glass Micro Machining by SACE (Spark **A**ssisted **C**hemical **E**ngraving)



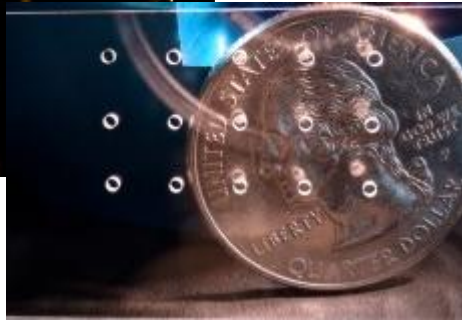
Why Micromachine Glass?



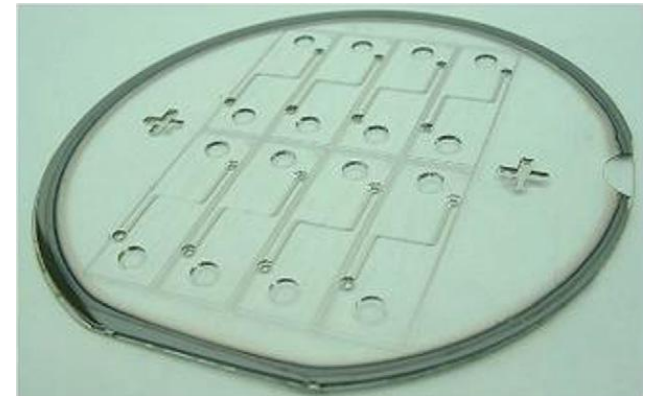
Glass Micromachining Techniques



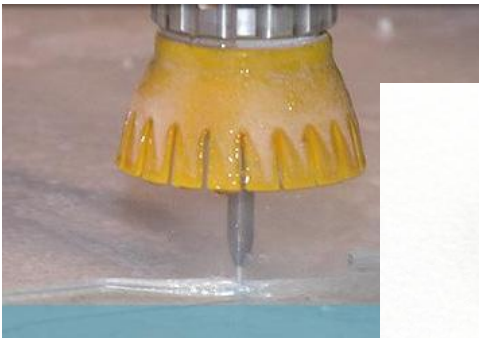
Thermal (e.g. laser)



Chemical (e.g. HF etching)



Mechanical (e.g. diamond tool drilling)



DILLMEIER
GLASS COMPANY

Glass Micromachining in a Nutshell

Mechanical (mechanical drilling, USM, AJM, ASJM)

<i>Features</i>	<i>Limitations</i>
• Flexible (mech drill/ USM) • No tool wear (AJM / ASJM) • Batch process (AJM) • Lean process	• Tool wear (mech drill / USM) • Rough surfaces • Chipping, exit cracks • Low aspect ratio (AJM / ASJM) • Mask required (AJM) • Frosted area (ASJM) • Moderate speed drilling

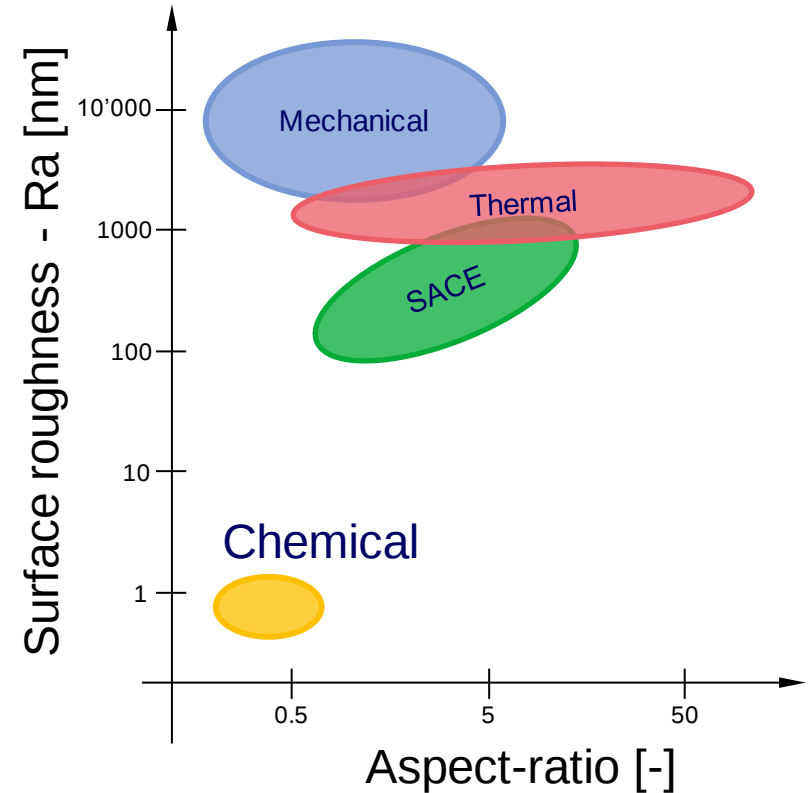
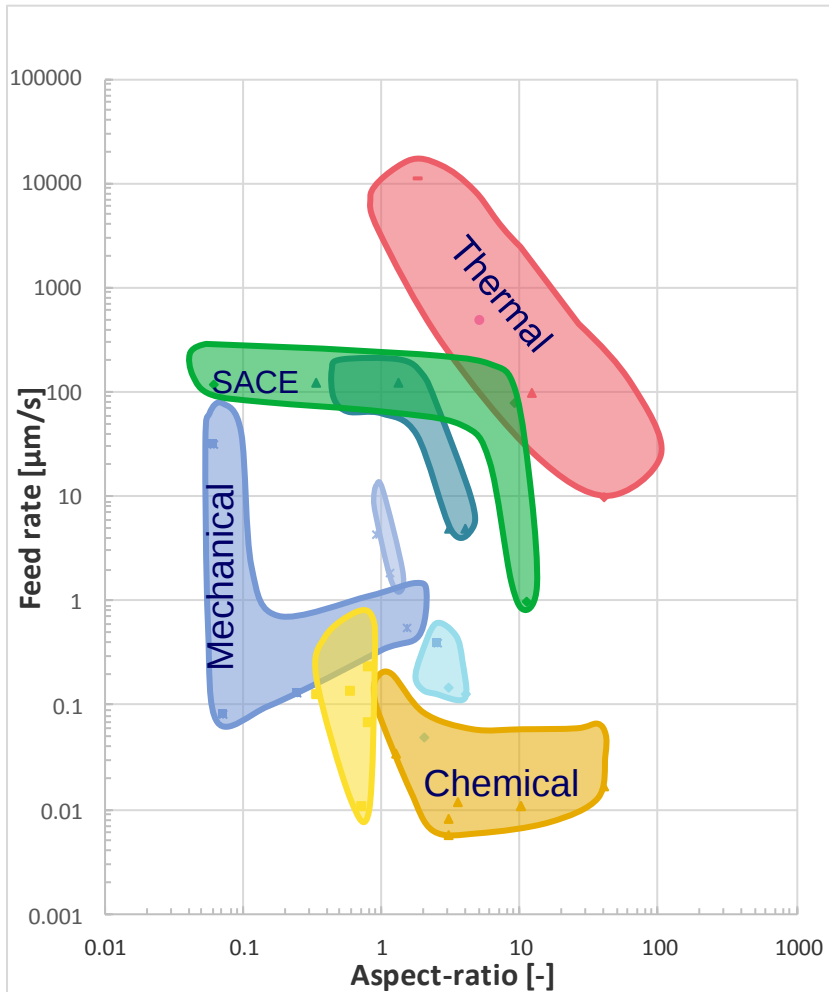
Thermal (Laser drilling, FEDM)

<i>Features</i>	<i>Limitations</i>
• Flexible (no mask) • High aspect ratio • High speed drilling • No tool wear	• Bulges (debris) • Heat Affected Zone (HAZ) • Microcracks • Chipping • Specific types of glass • Expensive equipment

Chemical (Wet etching (HF) + DRIE)

<i>Features</i>	<i>Limitations</i>
• Smooth surfaces (very low R_a) • High detail (small structures) • Batch process (mass-fabrication) • No HAZ • No microcracks	• Low aspect ratio (<i>wet etching</i>) • Extremely hazardous etchant • Many process steps • Slow etch rate • Requires a clean room

Glass Micro-drilling



Excluding expensive chemical etching technologies, SACE gives best surface quality at high drill rate

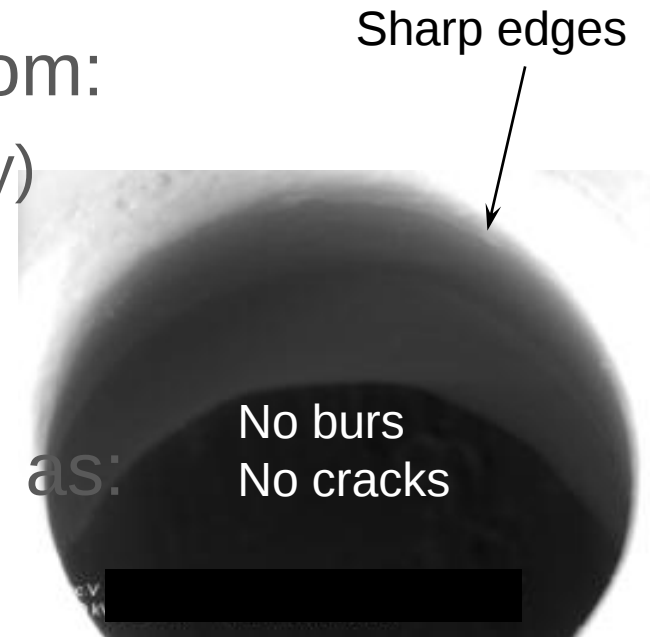
SACE – The Hybrid Process

SACE combines advantages from:

- Chemical (good surface quality)
- Thermal processes (Speed)

While avoiding drawbacks such as:

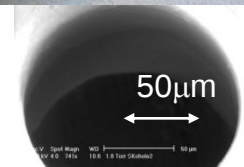
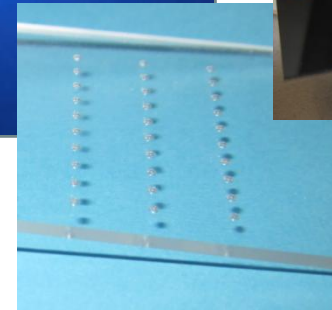
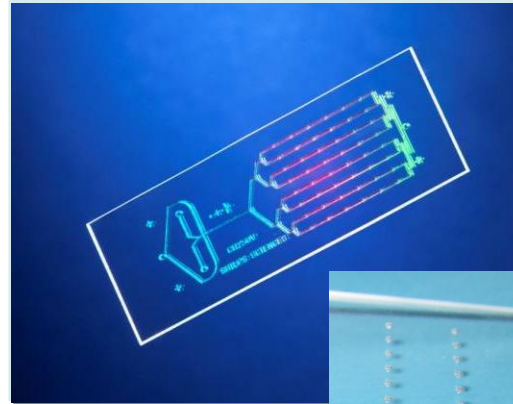
- Microcracks
- Burs
- Masks
- Highly toxic chemicals



SACE a versatile technology

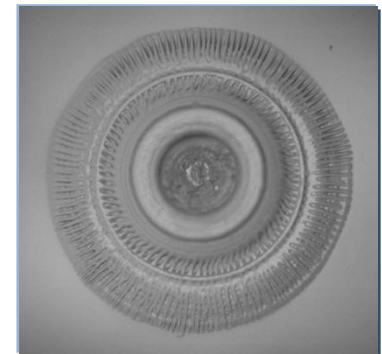
SACE technology allows

- Drilling ($\varnothing$ 150 μm , 1:10)
- Cutting (3 mm)
- Milling
- 2.5D machining
- Texturing



SACE technology is

- Clean room compatible (e.g. bonding)
- Fast (faster than traditional glass machining technologies)
- Mask less process
- Lean process (very low tool wear)
- Applicable to all SiO based materials



Micro-drilling and engraving with SACE

Technology

- SACE : Spark Assisted Chemical Engraving on glass
- DC generator
- Regulation by micro force
- Electrolyte management
- 4 - 5 axes machine
- Siemens 840D

Patented

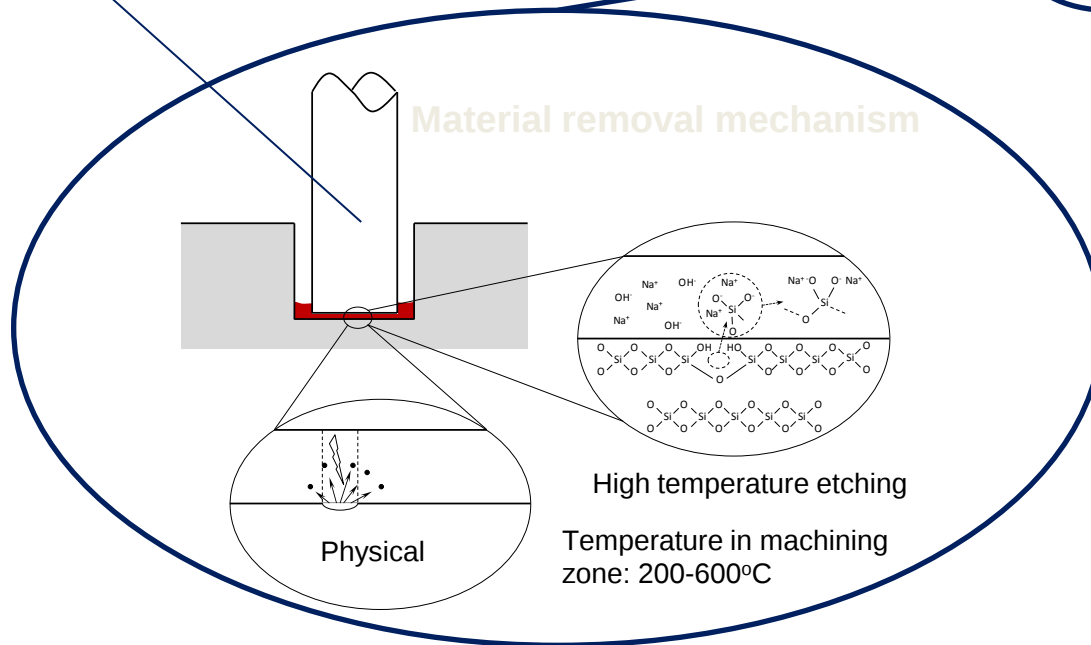
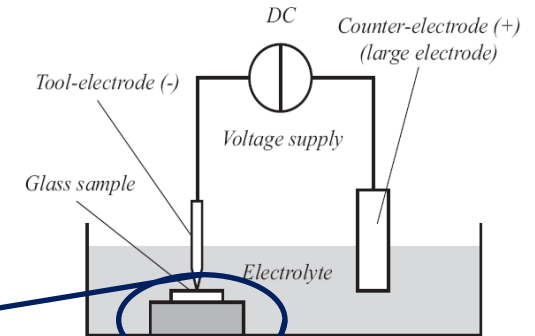
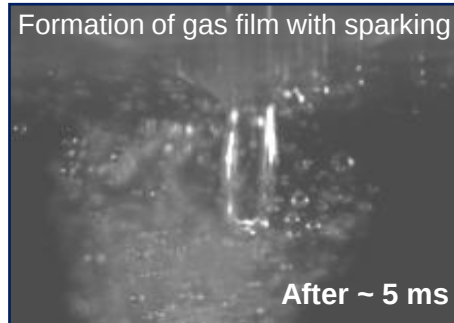
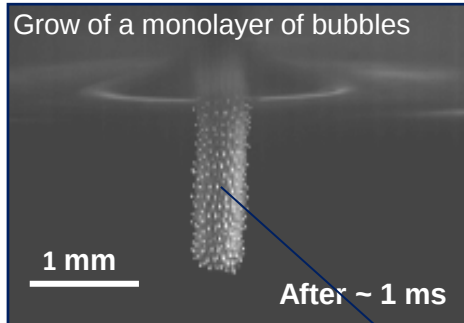
Machine configuration

- Mono-Head machine
- Mutli-Head machine
- Customized workpiece holders

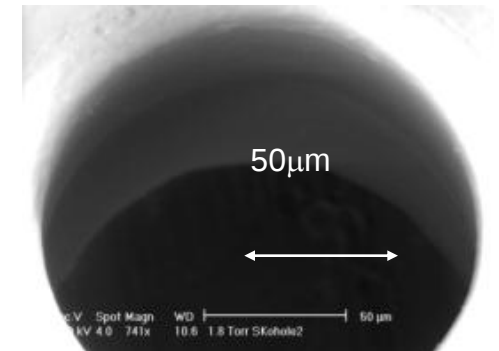
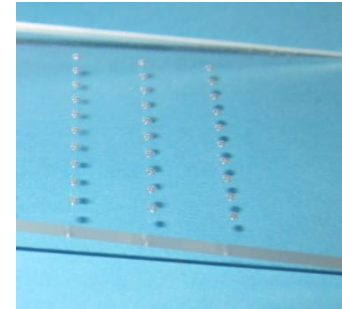
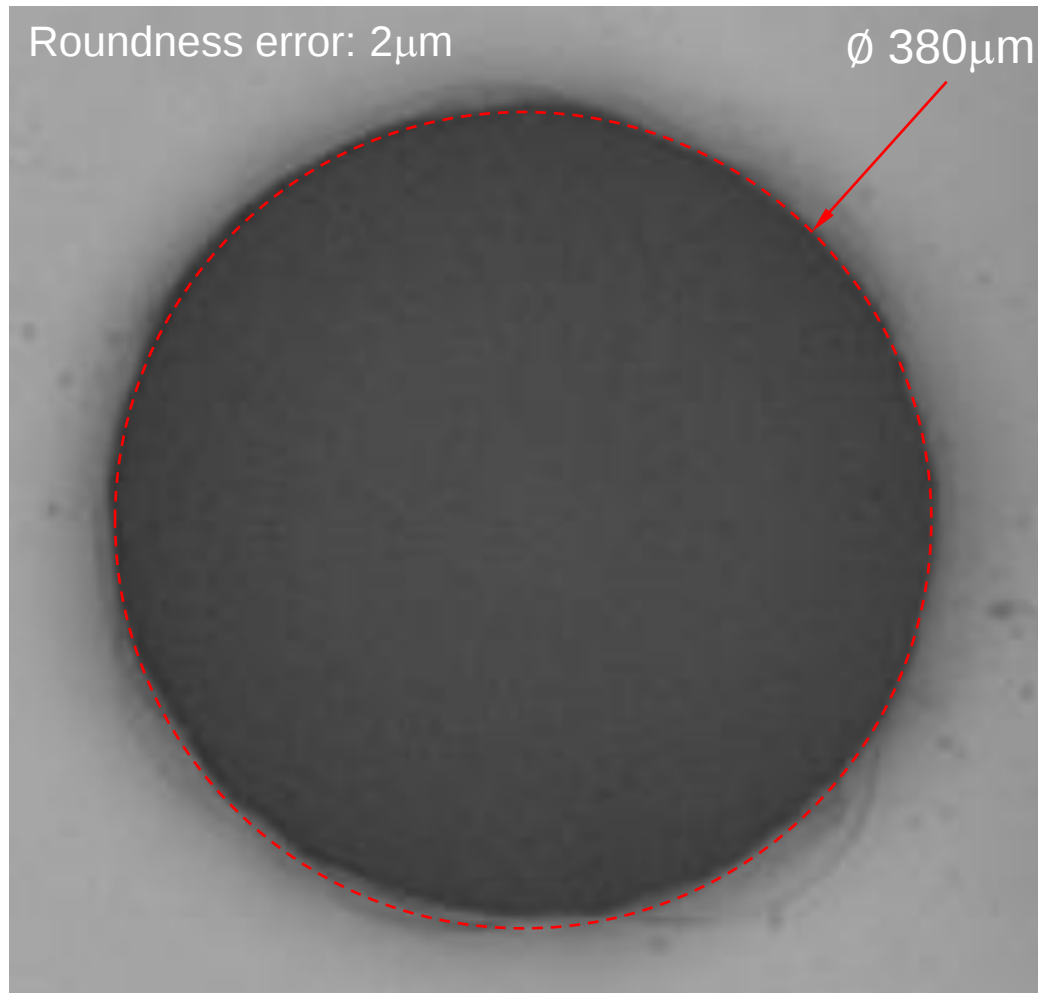


SACE is thermally assisted chemical etching

Heat source: sparks through electrochemically formed gas film

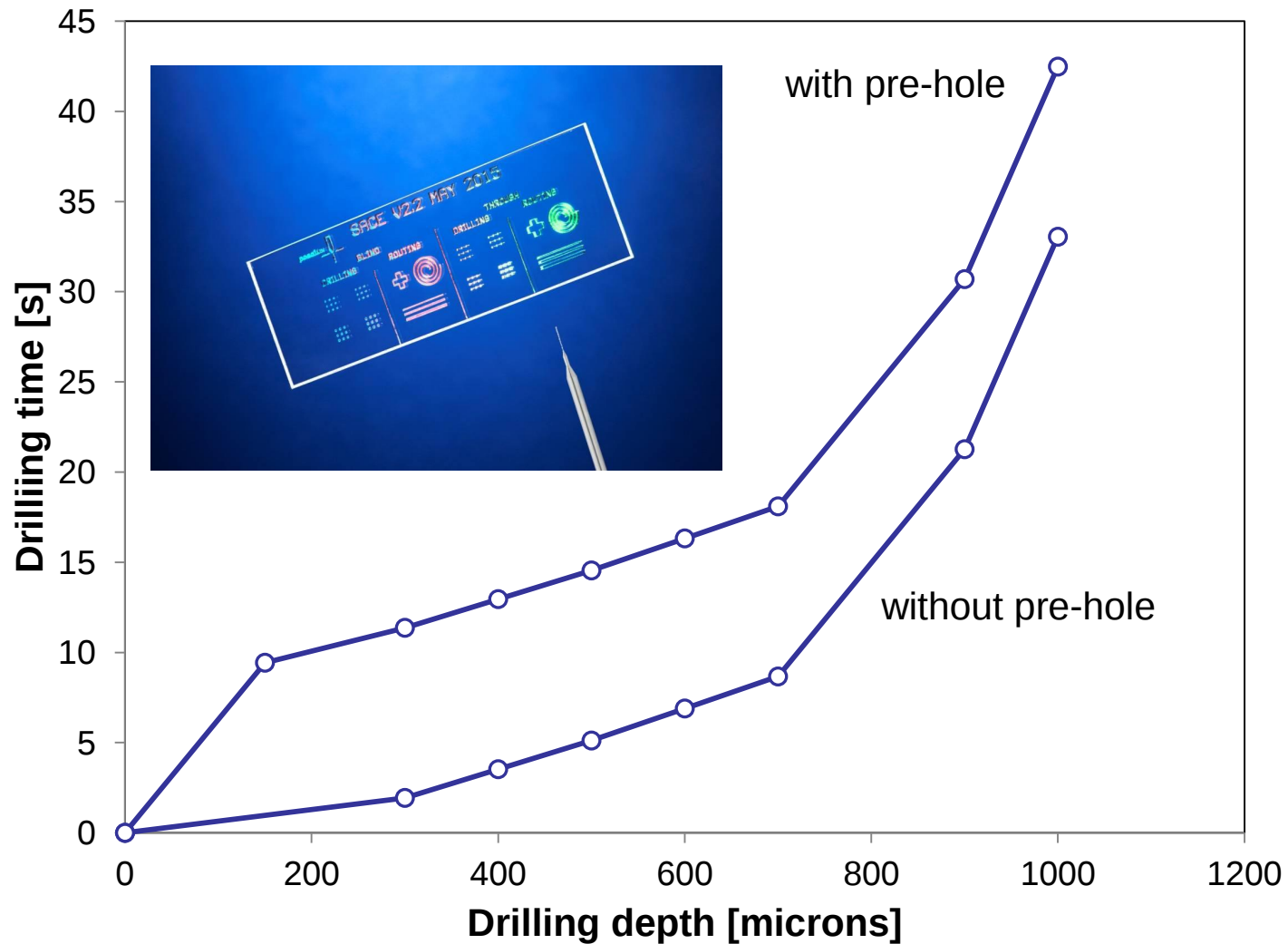


Micro-drilling of glass

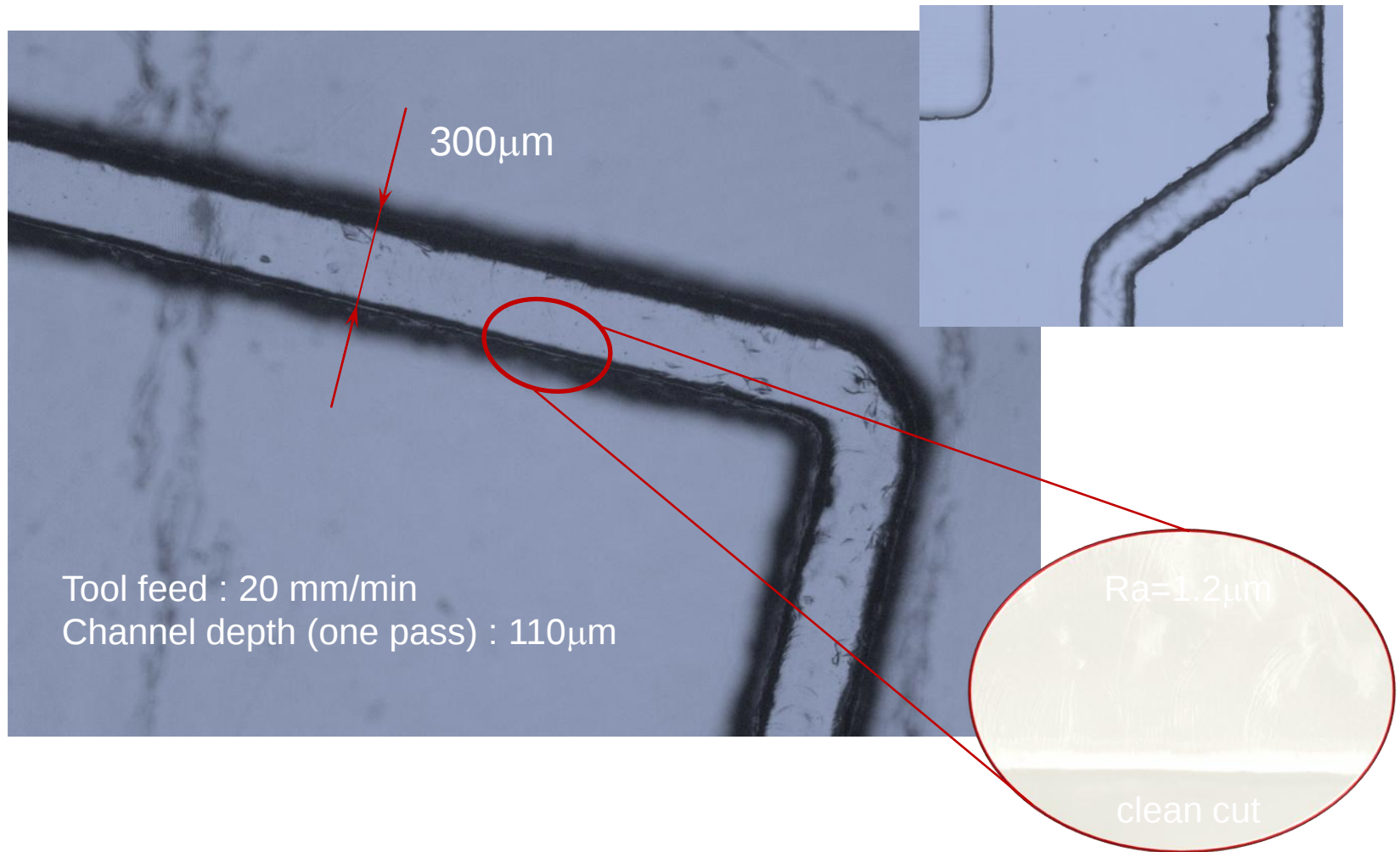


1mm deep
1:5

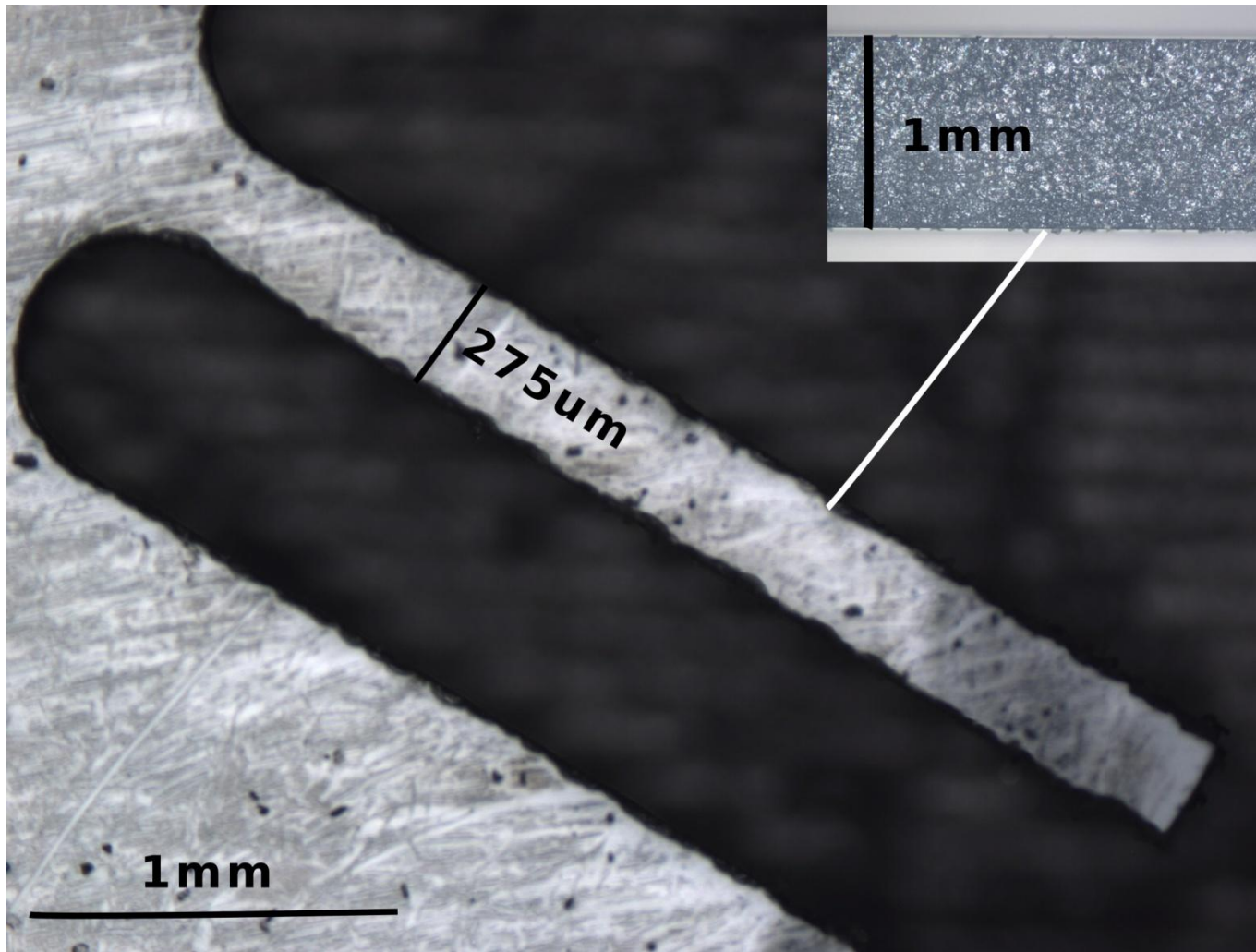
Typical drilling times – 4 Spindles



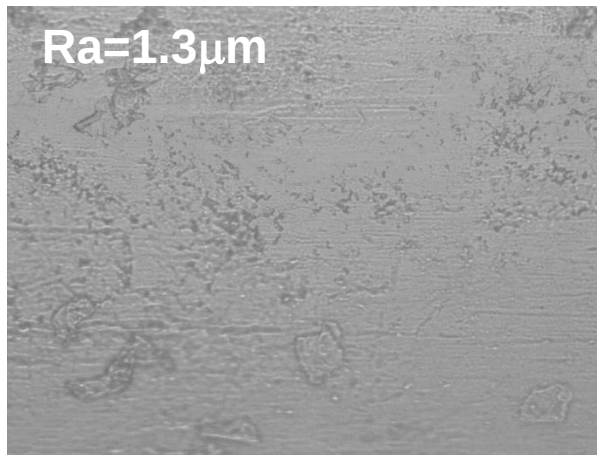
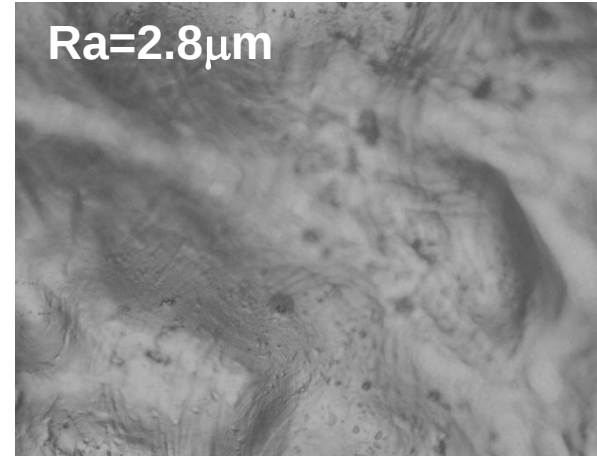
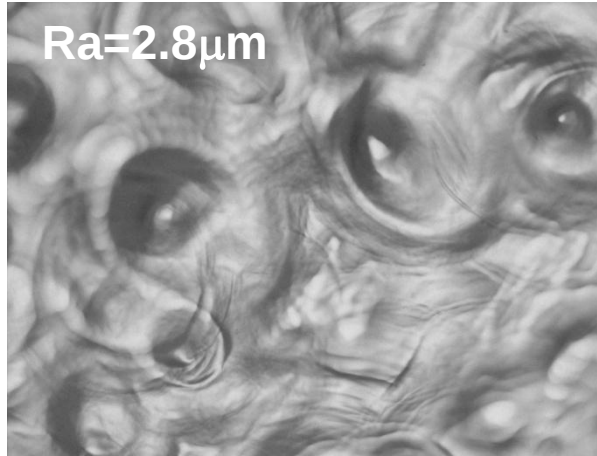
Micro-milling of glass



Micro-cutting of glass



Examples of cut surface qualities



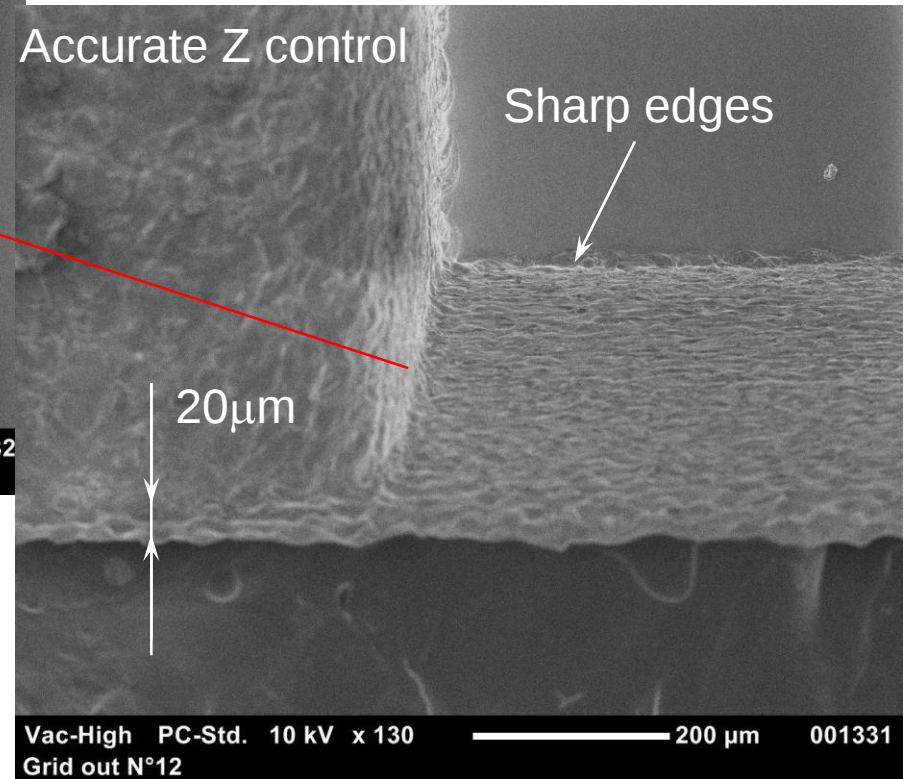
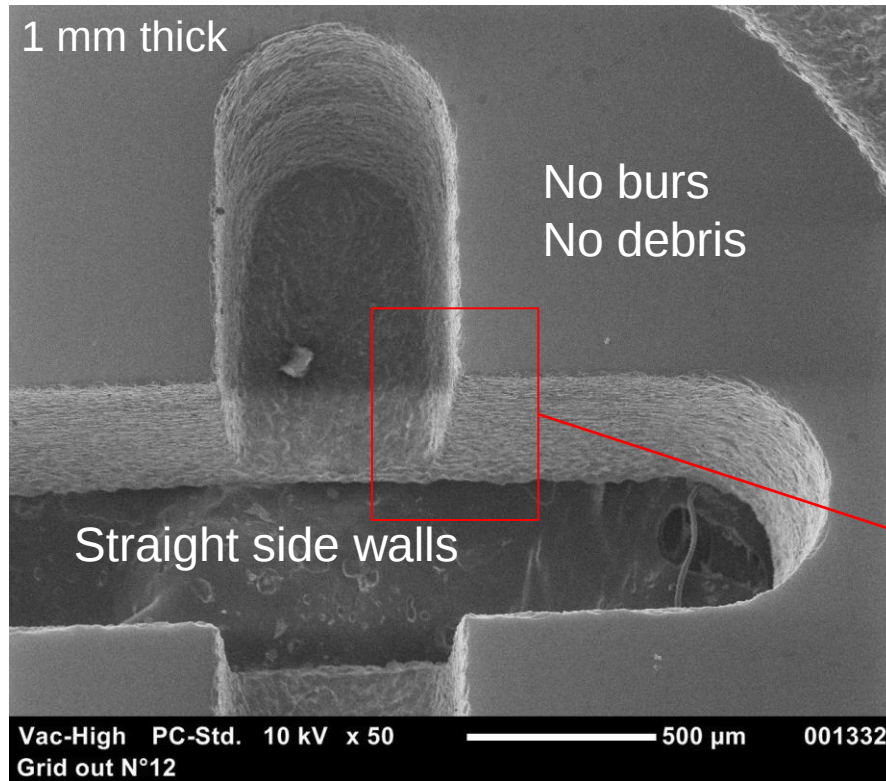
Typical cut parameters:

Tool feed : 15 mm/min

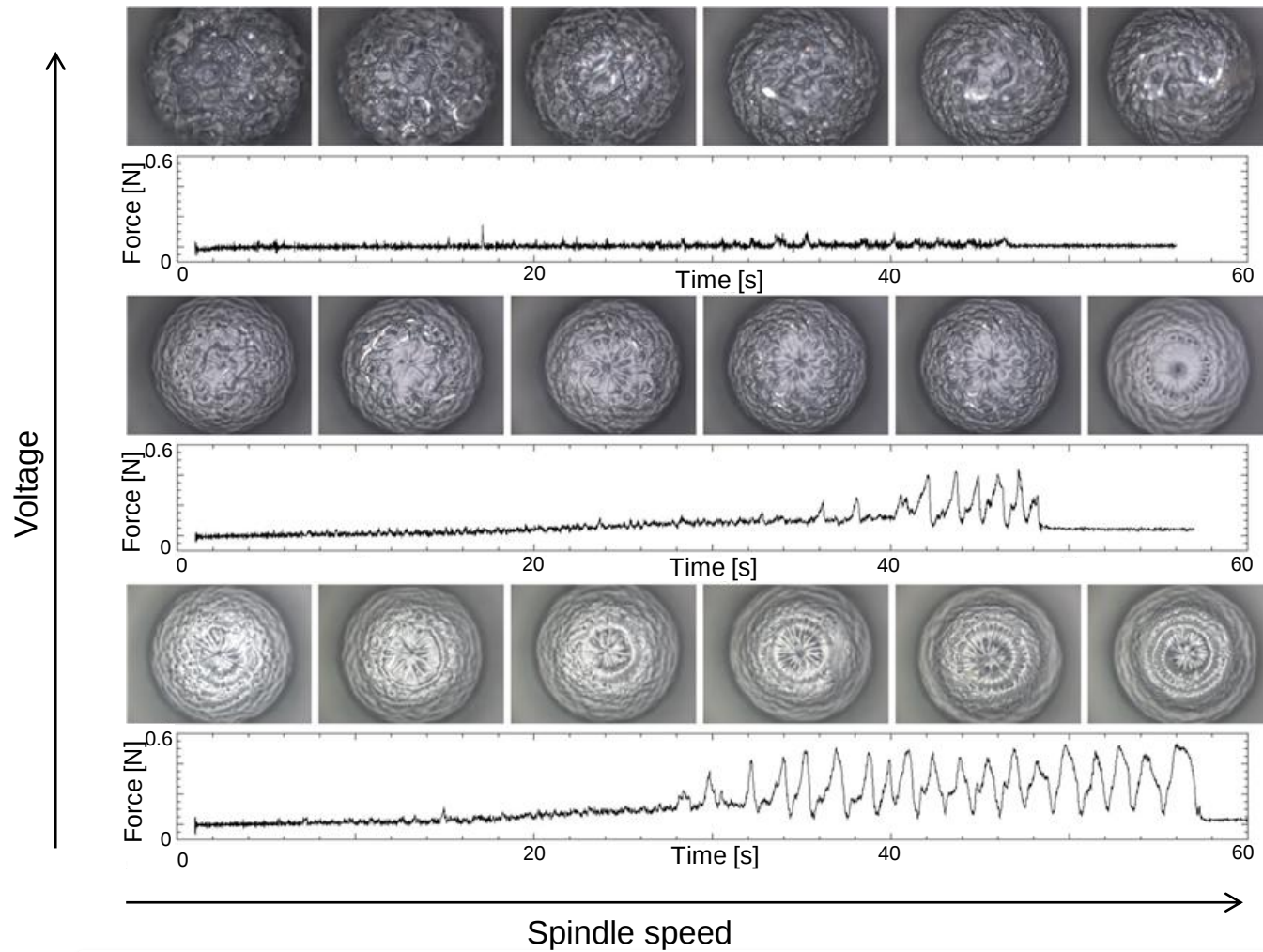
Cut depth : 80 μ m/pass

No micro-cracks

2.5D machining of glass

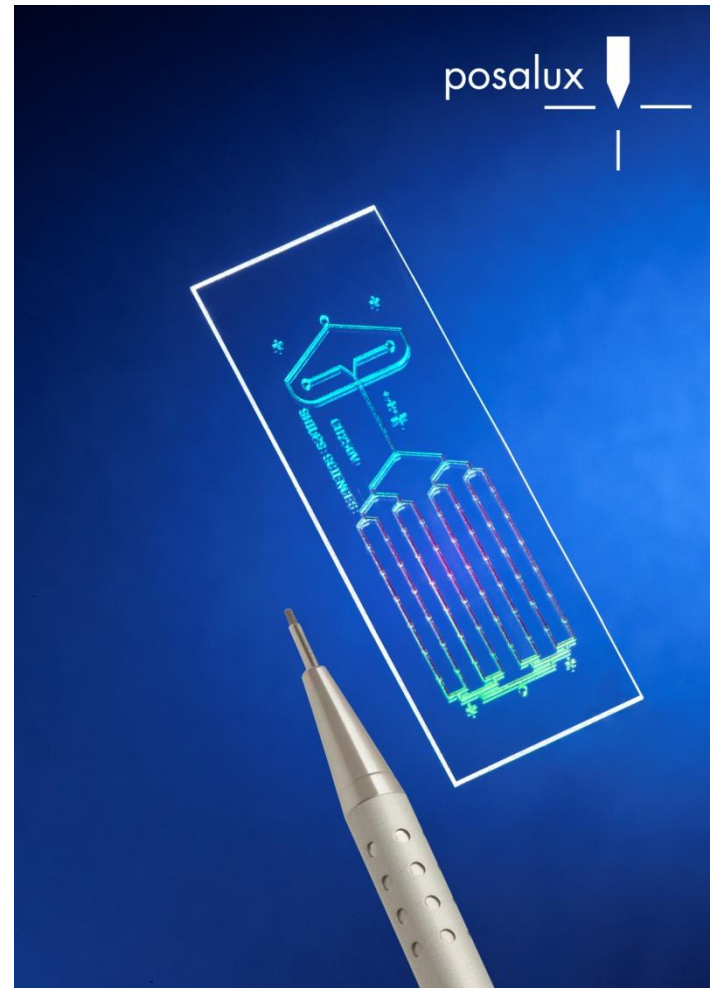
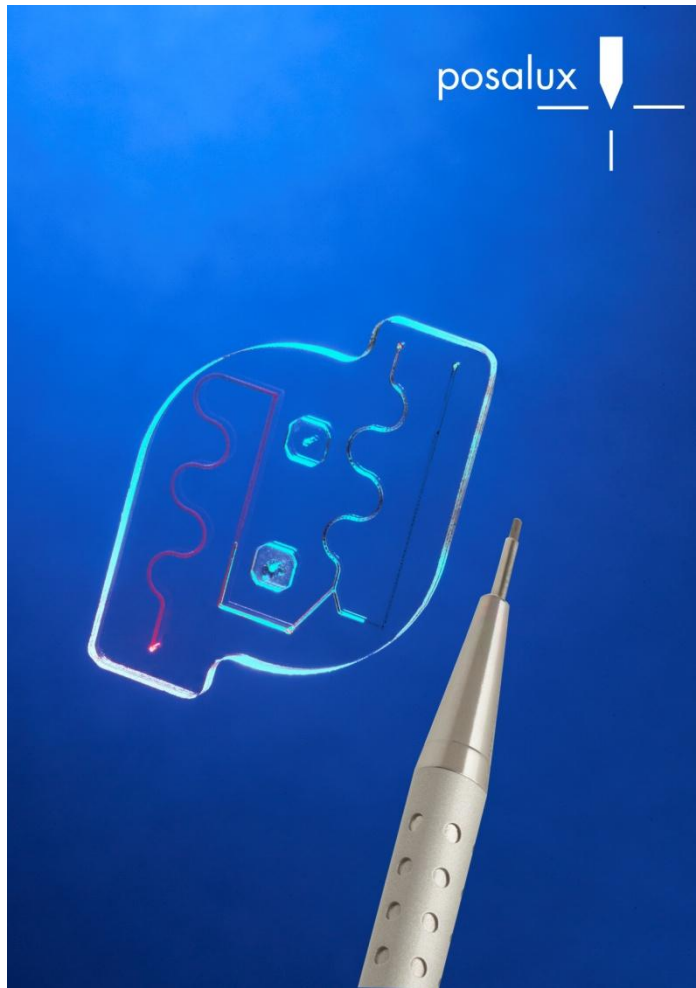


Microhole texturation

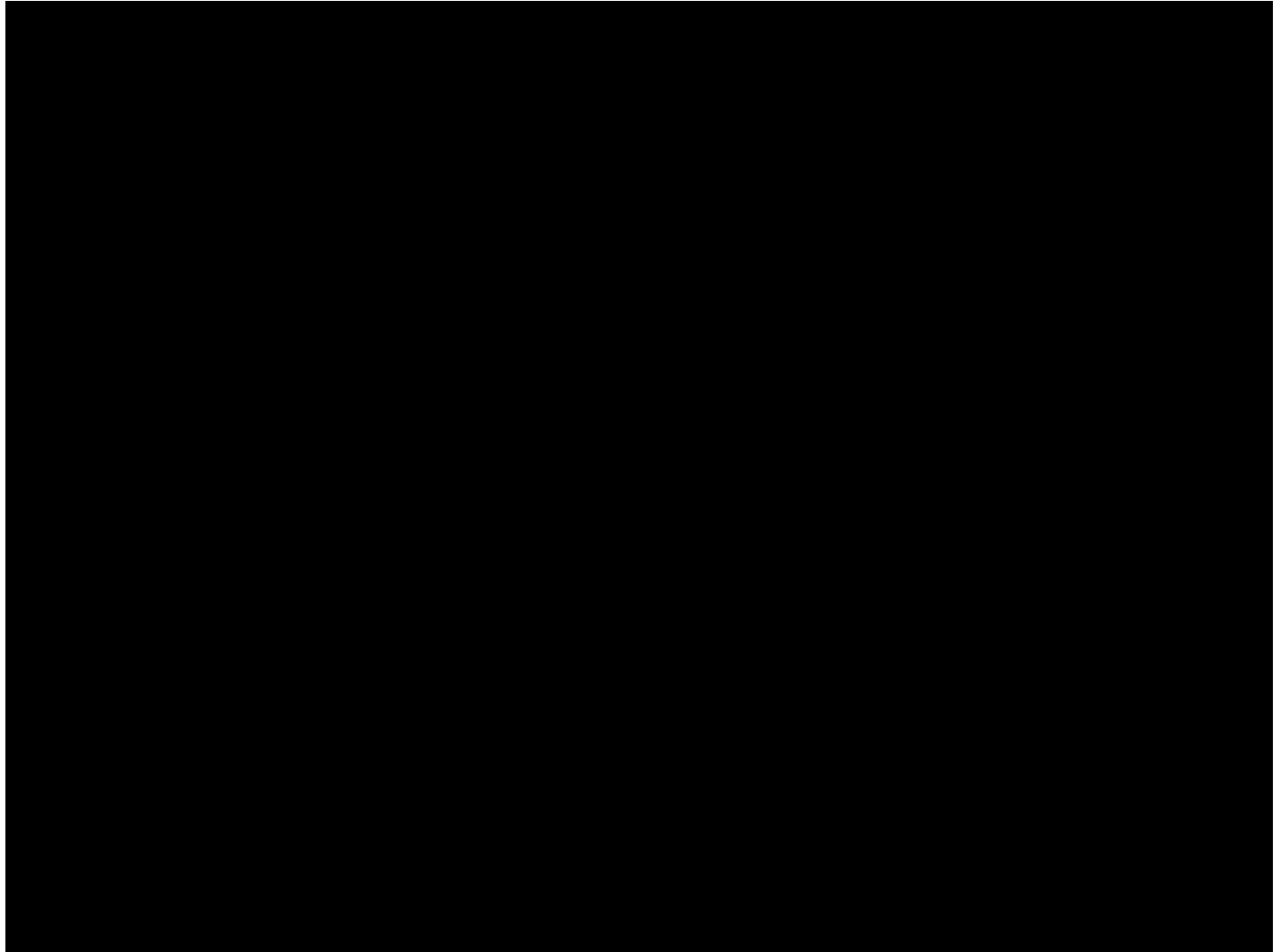
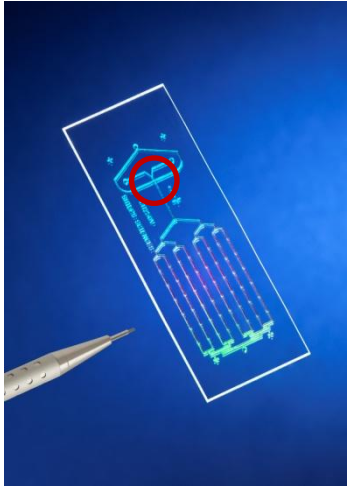


Different machining settings generate different controlled surface patterns

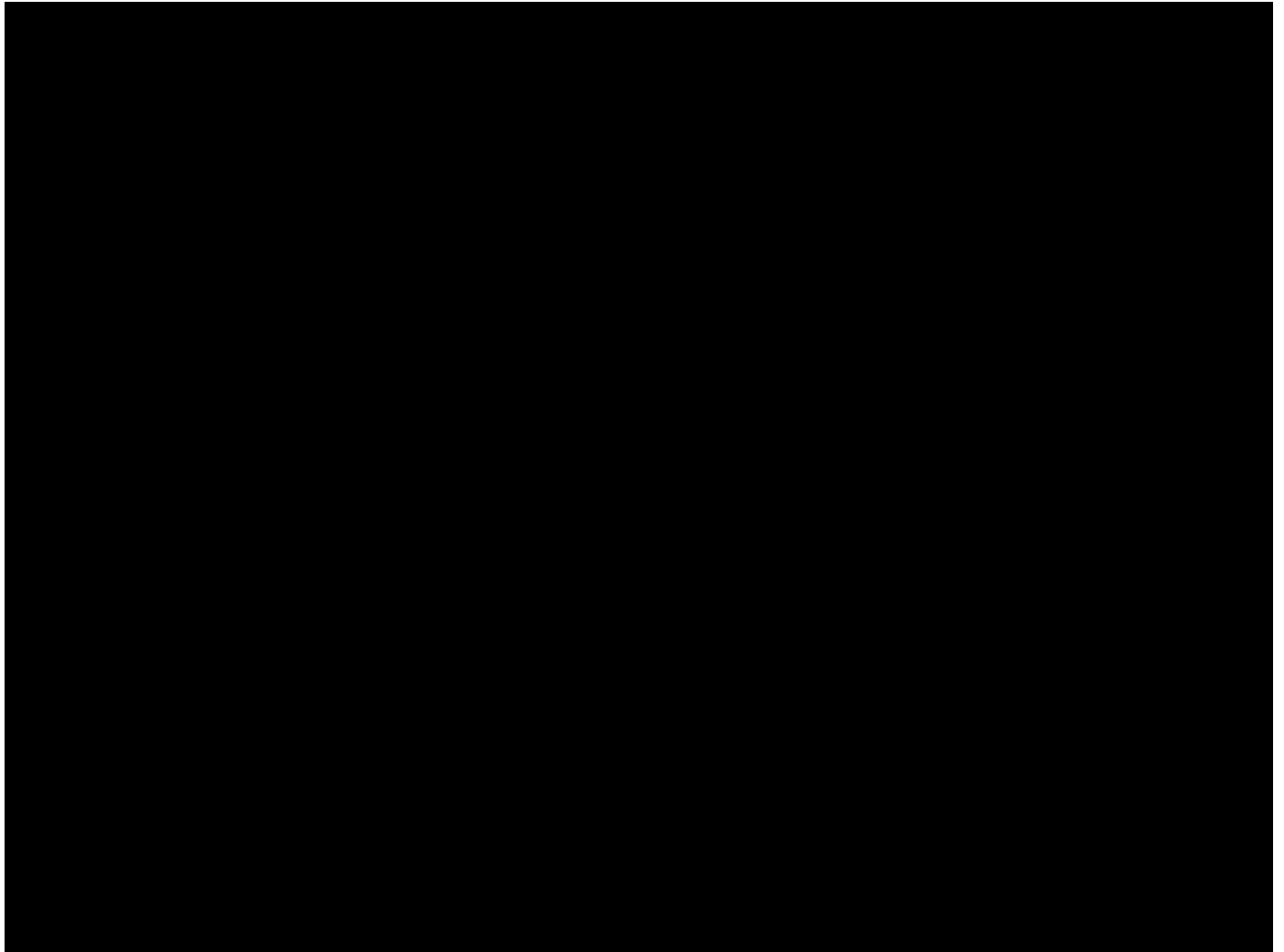
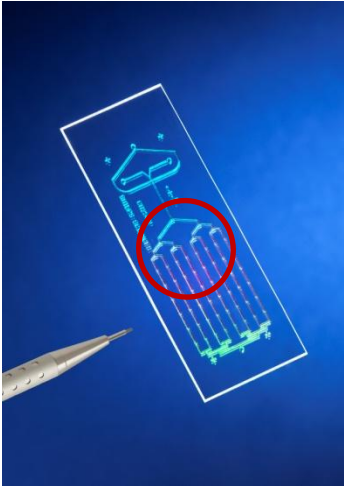
Two application examples



Micro-droplets generation



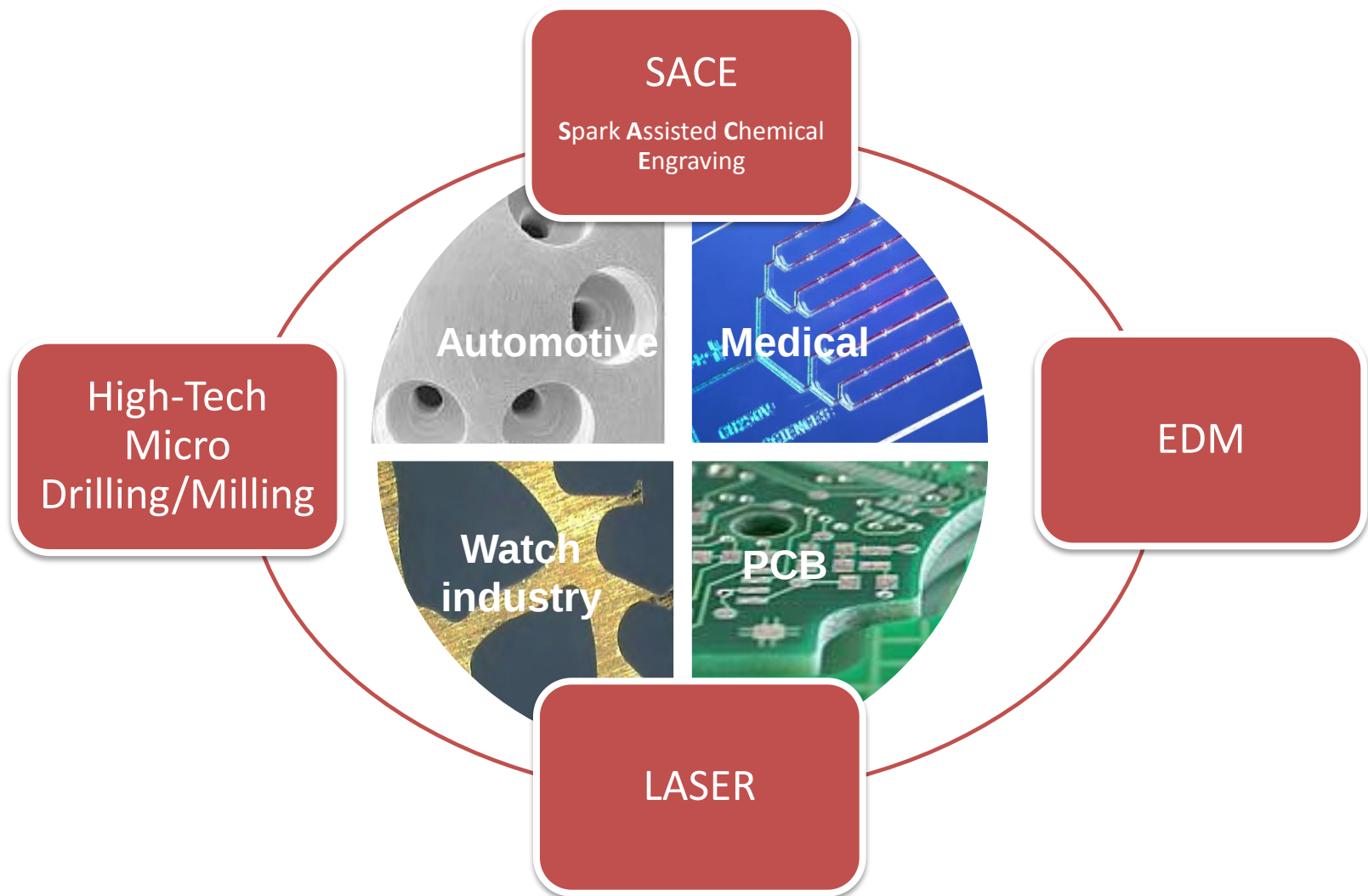
Micro-droplet distribution



What Posalux offers to promote our technologies



Four technology families for four markets



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Appendix
